

Superconducting Materials for Undulators

M.D. Sumption

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Symposium on Novel SC Materials and Technology

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Outline

- Undulators
- Superconductors
- Undulator Needs wrt SC
- Superconducting Materials
 - NbTi, APC, Nb₃Sn, Nb₃Al, MgB₂, YBCO, Bi-2212, Oxypnictide
- Focus on APC for Undulators
- Focus on Nb₃Sn Development for Undulators
- Issues: J_c , J_e , J_w , Stability, Insulation
- Summary

Undulators

- Magnet structures which cause electrons to have undulatory paths, generating radiation, and can be of various type (helical, planar)
- Made with permanent magnets, or electrical conductors
- In the latter case, field, and performance, dictated by current density
- Normal conductors can be used, but superconductors achieve the highest current density in the windings, and thus can lead to undulators with high fields, and thus high performance
- To first order then - its about current and current density in the wire!

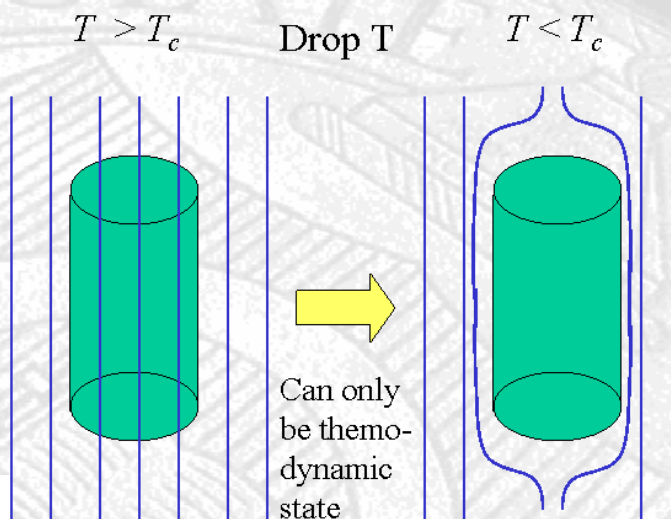


- **What, then, are superconductors?**
- **What are their flavors?**
- **What do Undulators require of them, and how do they measure up?**

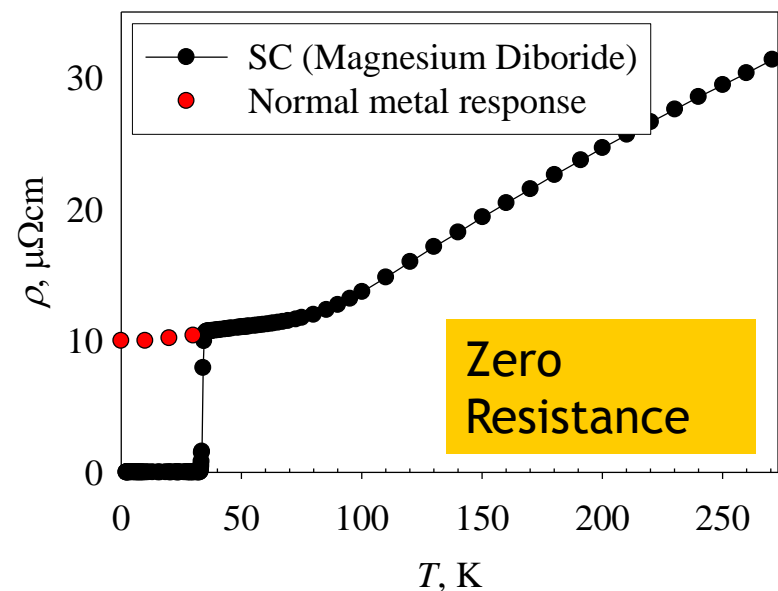
(1) Superconductor Properties

Superconductivity begins with a small attractive interaction term between electrons (sometimes E-P)

This leads to Cooper pairing of electrons, a collective state, and an “energy gap”

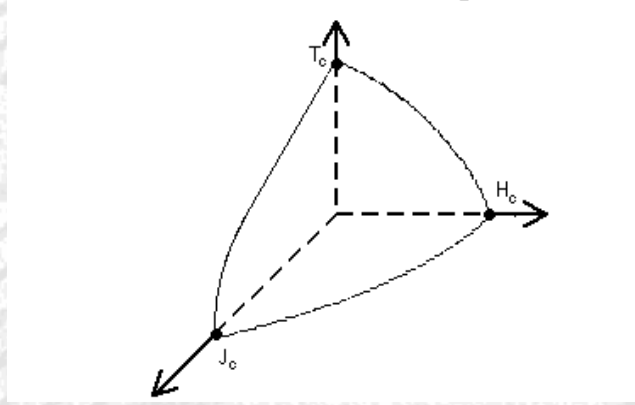


Magnetic Flux exclusion; full or partial (vortices)



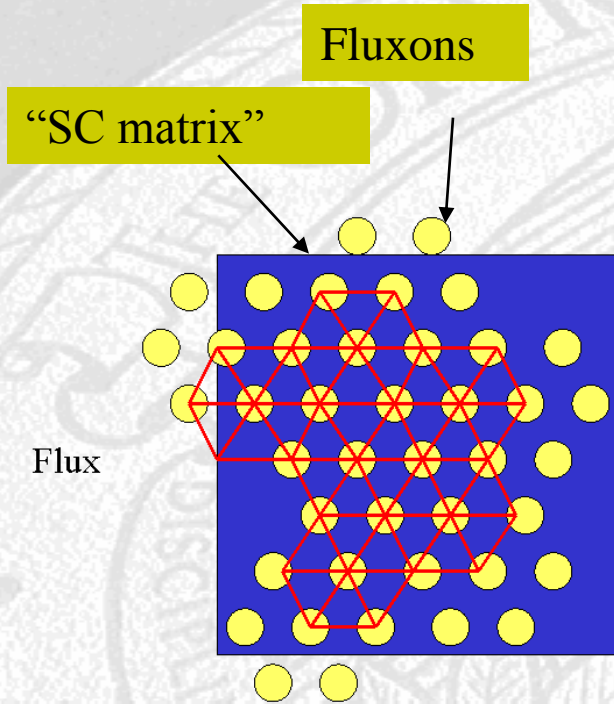
Zero Resistance

Critical Surface Phase Diagram



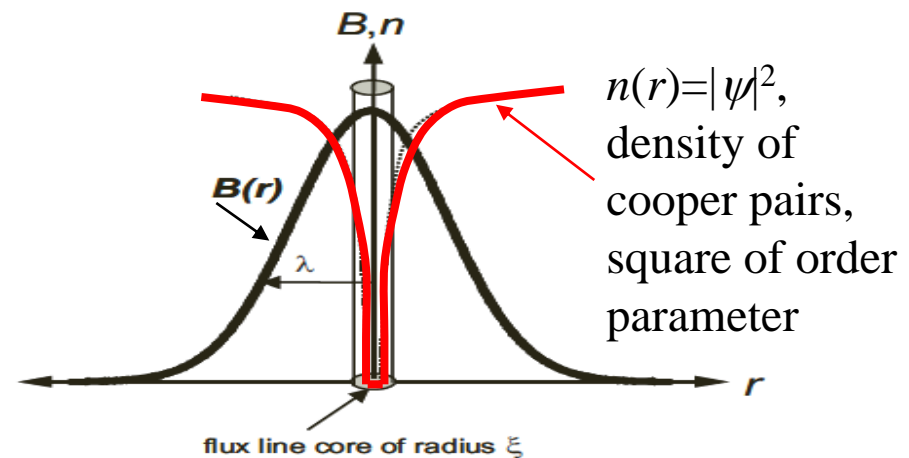
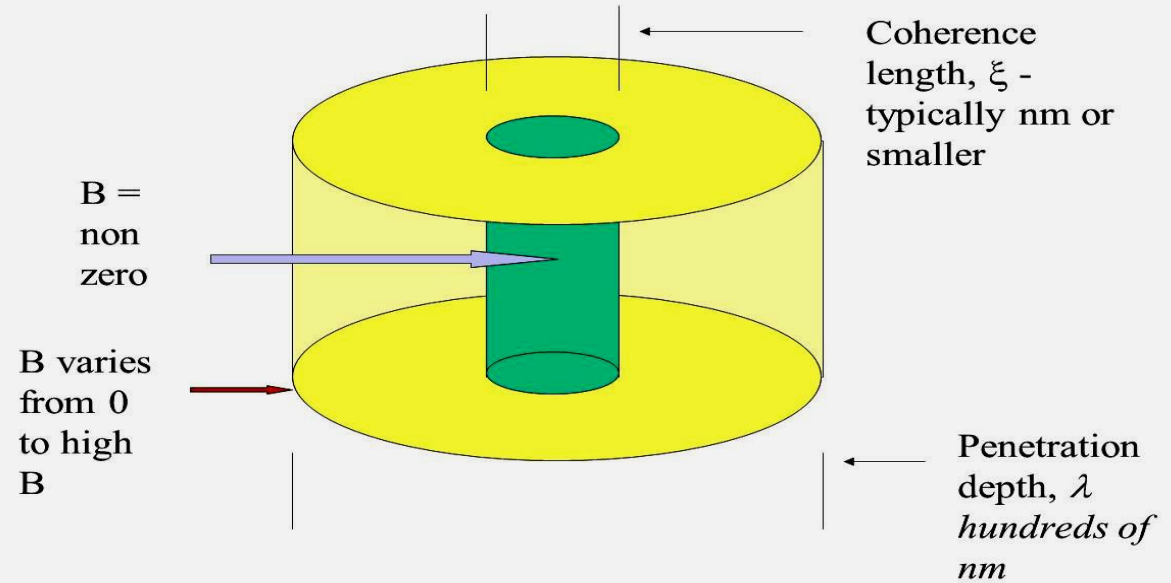
Superconducting properties below a critical Temperature (T) Field (B) Current density (J) surface

(2) Quantized Flux Vortices, and two length scales



If B is present, it is as quantized vortices in a triangular array

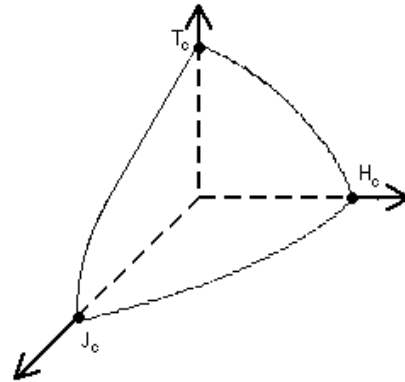
Structure of a Fluxon



(3) Magnetic Phase Diagram of Superconductors and Concept of Pinning

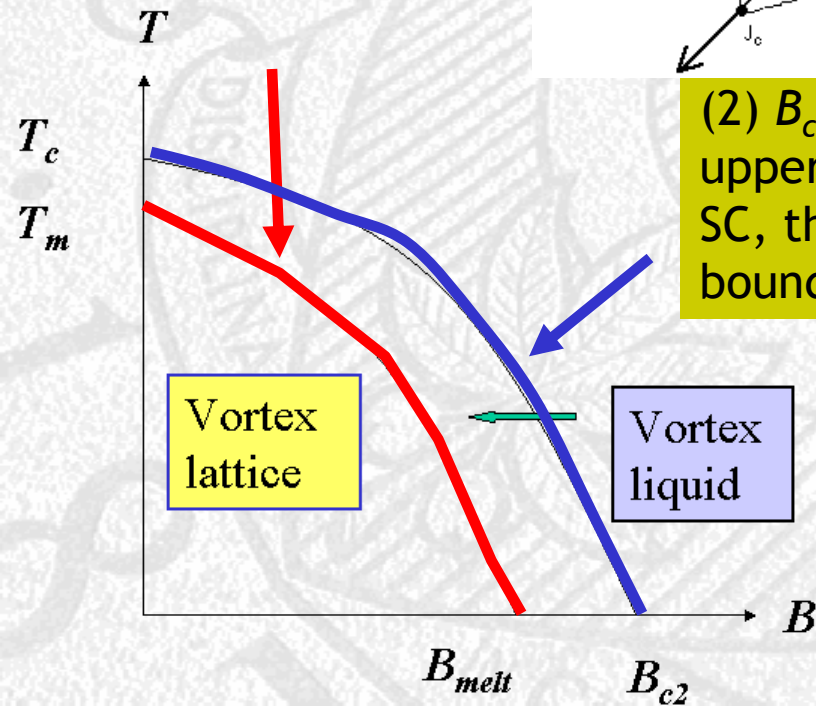
(1) T_c is the limiting temperature of operation

Critical Surface Phase Diagram

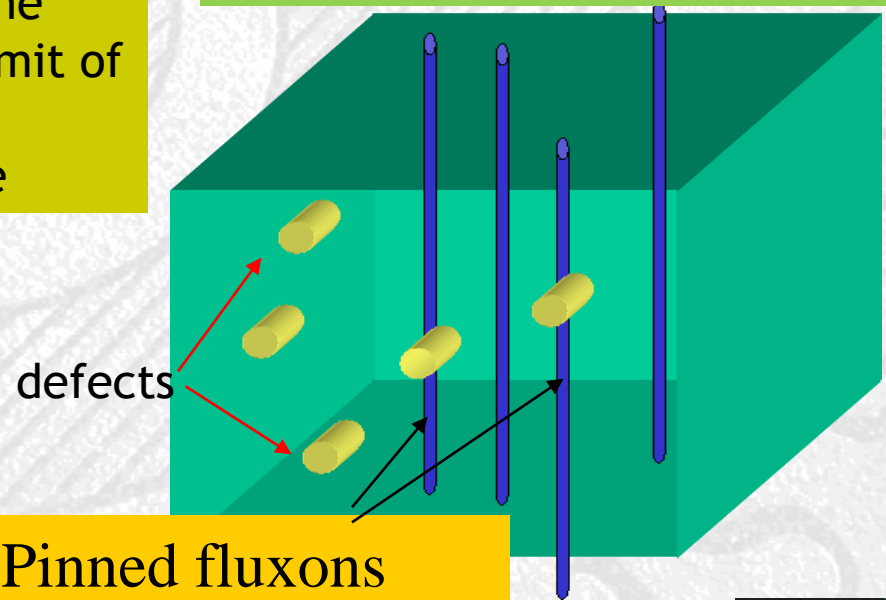


(3) Defects are needed to pin the fluxons that enter the SC to maintain SC

The third critical parameter is limiting current density - which is where we will focus



(2) $B_{c2}(T)$ is the upper field limit of SC, the SC boundary line

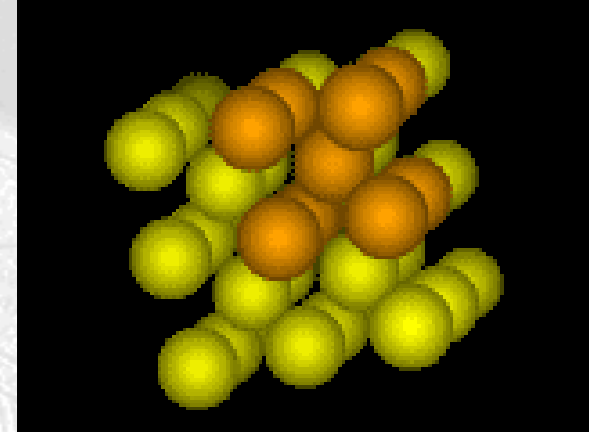
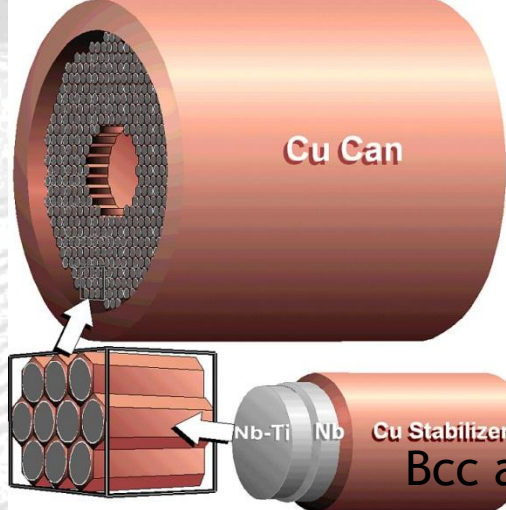


Practical SC Materials

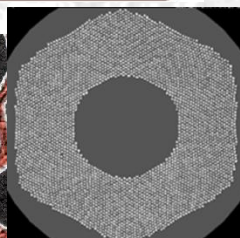
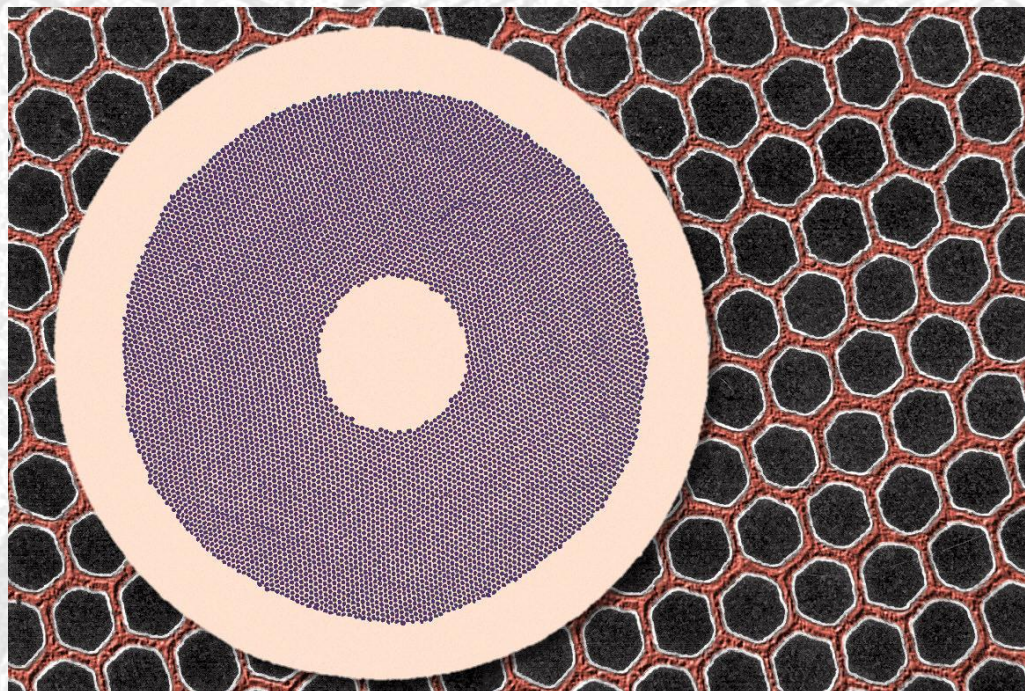
- Solid Solution Alloy: **NbTi** (9 K, Bc2 13.5 T)
- Intermetallic compound: **Nb₃Sn** (18 K, 25 T)
- **BiSrCaCuO - 2212 and 2223** [High T_c (110 K), **layered**, high Bc2, moderate fab difficulty]
- **YBaCaCuO - 123** [High T_c (90K), **less layered**, difficult to process]
- **MgB₂** [inexpensive, easy, 39 K T_c]

Example SC --NbTi

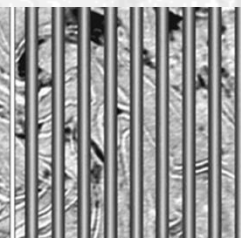
Filaments are about 5 microns, wire is about 0.8 mm OD



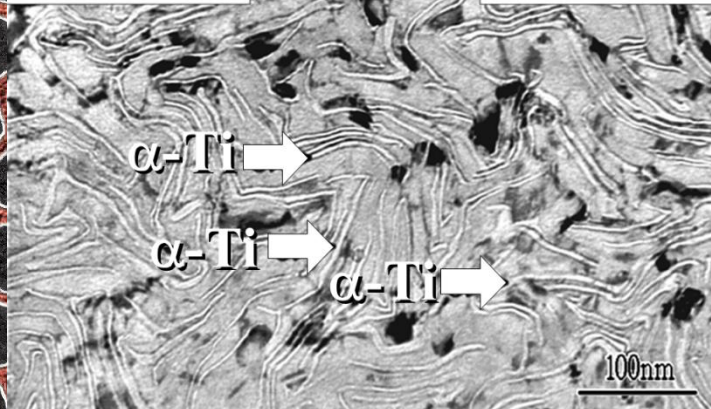
Inside a filament



Multifilamentary Cu/Nb-Ti Composite S.S.C. Wire in Transverse Cross-Section



Equilibrium Fluxoid Spacing at 5 T, 4.2 K



What do Undulators require of Superconductors

- Of course, the undulators must be operated below the T_c of the SC
- Mostly, however, they require a high level of current density of the SC, in order to reach the high performance undulators required
- Let us look at an example helical and an example planar undulator

Helical Undulator - ILC-like

Majoros

Supercond. Sci. Technol. 25 (2012) 115006

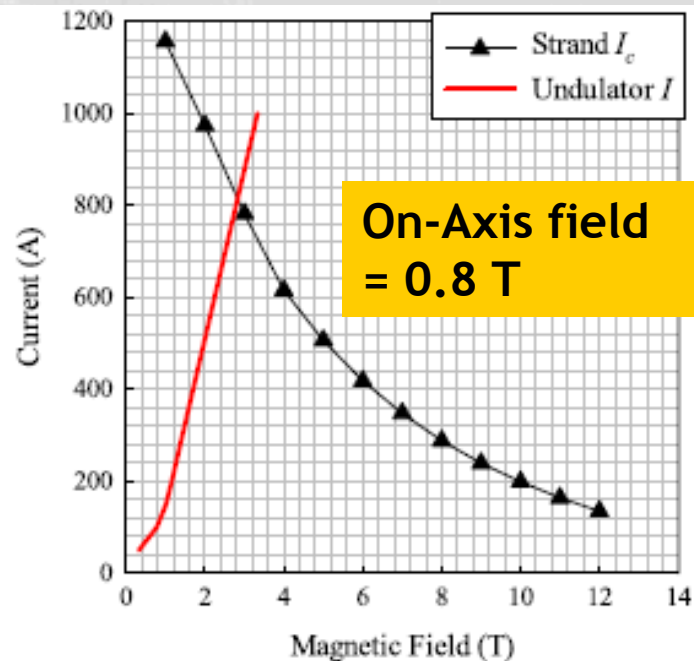
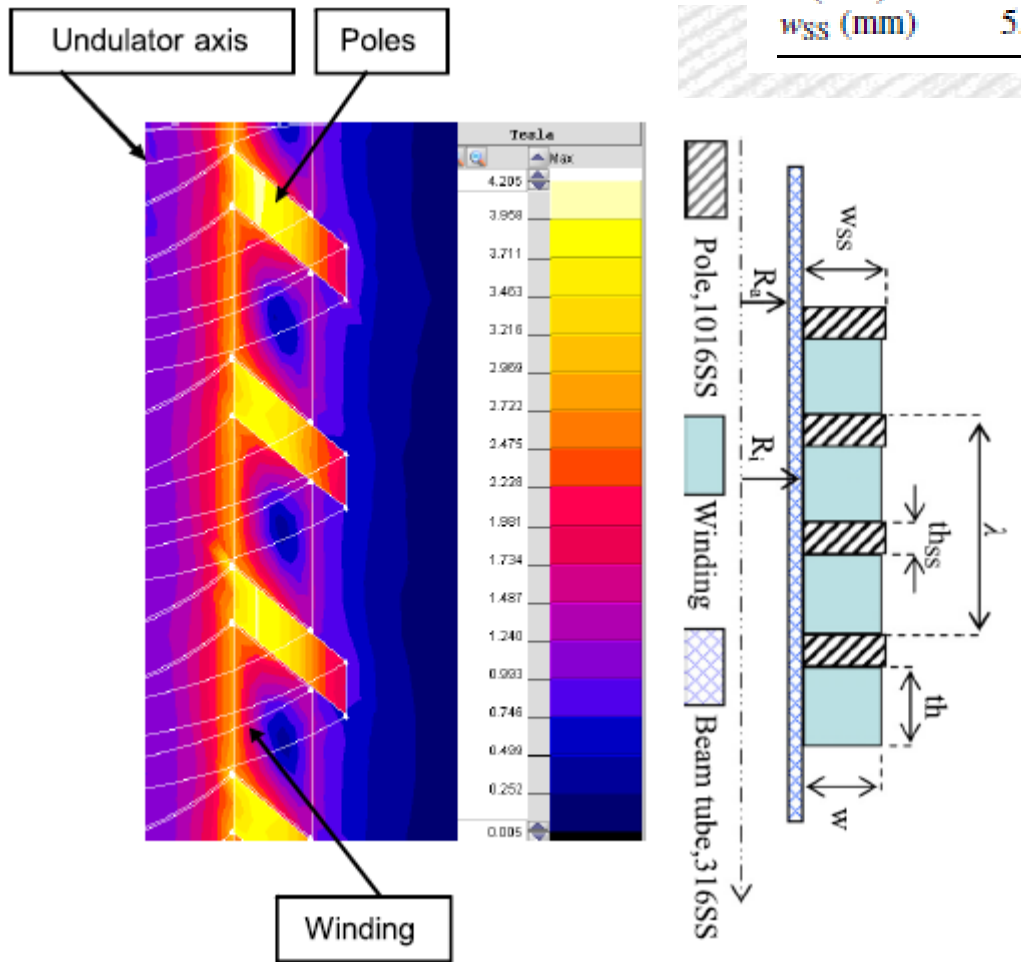


Figure 4. Load line of the undulator and a short sample $I_c(B)$ curve of the strand (\blacktriangle). Estimated critical current of the undulator = 815 A.

Table 1. Nb₃Sn strand specifications.

Outside diameter (mm)	0.5
Number of filaments	217
Filament diameter (μm)	24
Effective diameter (μm)	35
SC fraction (%)	45.6
12 T $J_{c,non-Cu}$ (A mm^{-2})	2200
4 T $J_{c,non-Cu}$ (A mm^{-2})	7650
4 T J_e (A mm^{-2})	3825
4 T I_c (A) for 0.5 mm outside diameter	622.22

Definitions

- $J_{c,layer} = I / \text{Area of superconducting material}$
- $J_{non-Cu} = I / \text{area which is not stabilizer}$
- $J_e = I / \text{area of strand}$
- $J_w = I / \text{area of winding}$

Pushing for higher freq. in ILC-like Helical Undulators

- Pushing to 11 -12 mm requires 1 T
 - Pushing to 10 mm requires 1.07 T
- (Assuming $K = 1$)

TABLE 1. CONDUCTOR PARAMETERS

	Fusion	Tube	Future Tube
Non-Cu %	51	50	50
12 T $J_{c,non-Cu}$ (A/mm ²)	1172	2200	3000
4 T $J_{c,non-Cu}$ (A/mm ²)	5100	7650	10,460
4 T $J_{c,strand}$ (A/mm ²)	2550	3825	5230
4 T I_c (A) for 0.7 mm OD	1000	1500	2050

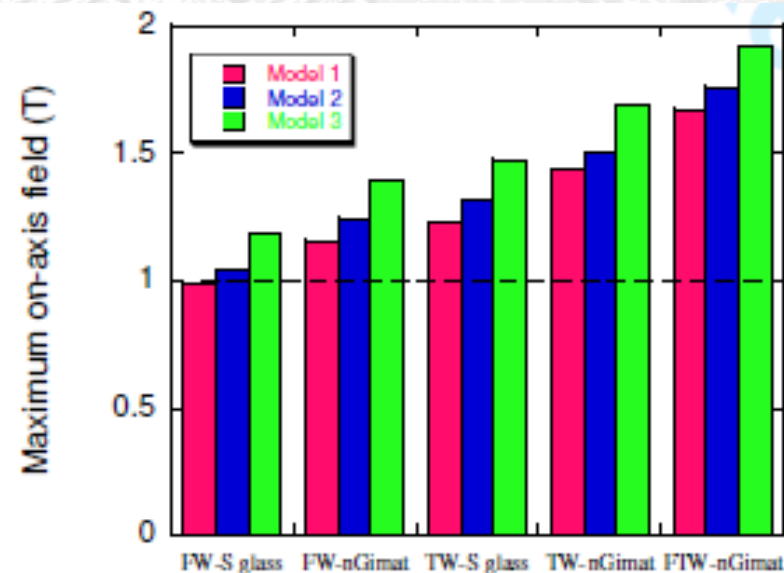


Fig. 9. Maximum on-axis magnetic field of the model undulators wound of different Nb₃Sn strands with different insulations. Straight horizontal dashed line indicates the 1 T requirement.

Majoros M *et al* 2010 *IEEE Trans. Appl. Supercond.* **20** 270



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Needs for Planar Undulators

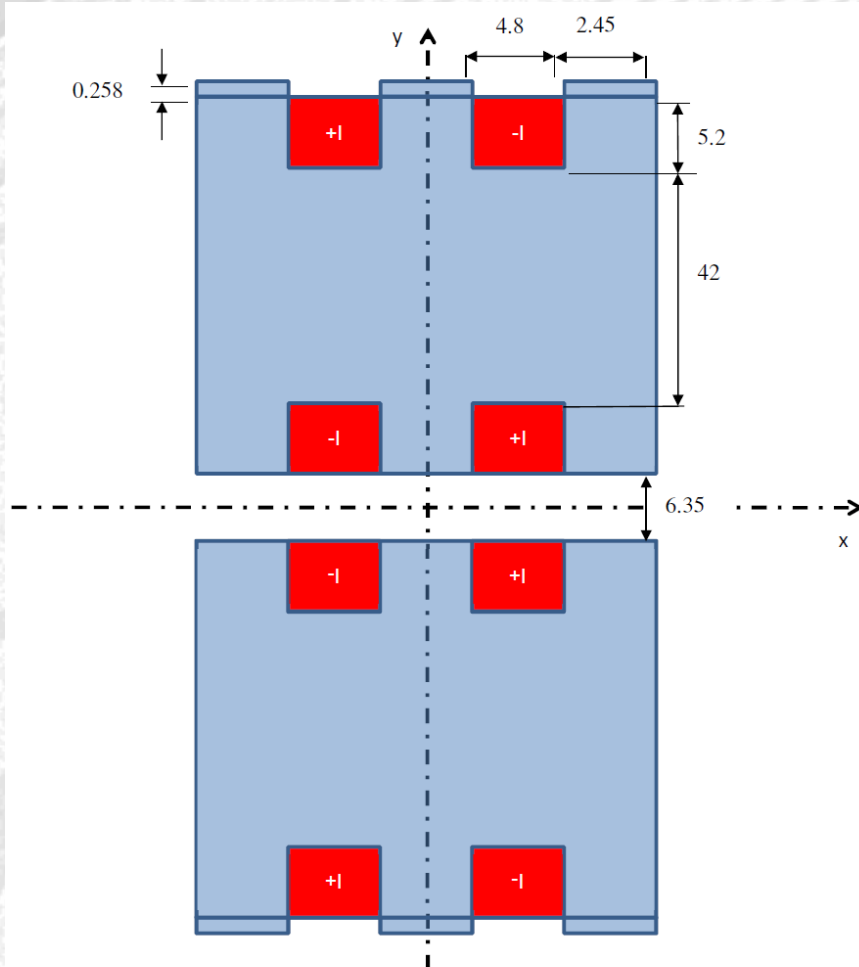
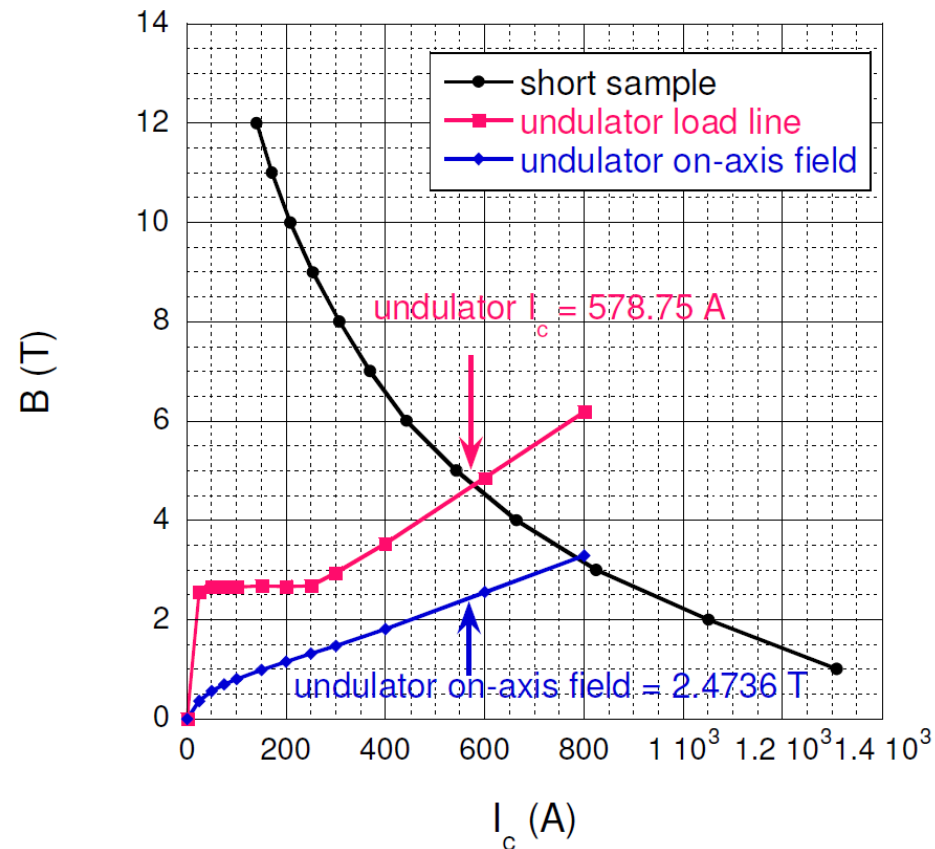


Fig. 3: Undulator cross-section (units: mm), period = 14.5 mm.



Conductor: Nb₃Sn tube-type 192 filament strand, 0.5 mm OD (not insulated), 0.65 mm OD (insulated)

Winding cross-section:, winding size 4.8 mm x 5.458 mm, 9 layers, number of turns = 60

$J_e = 2950 \text{ A/mm}^2$, 4.7 T

Translation to J_c

- For both Planar and helical, want something like
- $J_e = 3800 \text{ A/mm}^2$ 4 T
- $J_e = 3000 \text{ A/mm}^2$ 4.7 T

For Nb_3Sn , Ranging from 2550-5320 A/mm^2 4 T

But Assumed fill factor of SC in Nb_3Sn strand is 50% (can range 45-50%). Fill factor (λ) can vary for different SC)

So for targets, take $J_e = 4000 \text{ A/mm}^2$ at 4 T \rightarrow

For Nb_3Sn ($\lambda=50\%$), $J_c = 8000 \text{ A/mm}^2$

For NbTi ($\lambda=65\%$), $J_c = 6153 \text{ A/mm}^2$

For APC (assuming $\lambda = 30\%$), $J_c = 13,333 \text{ A/mm}^2$

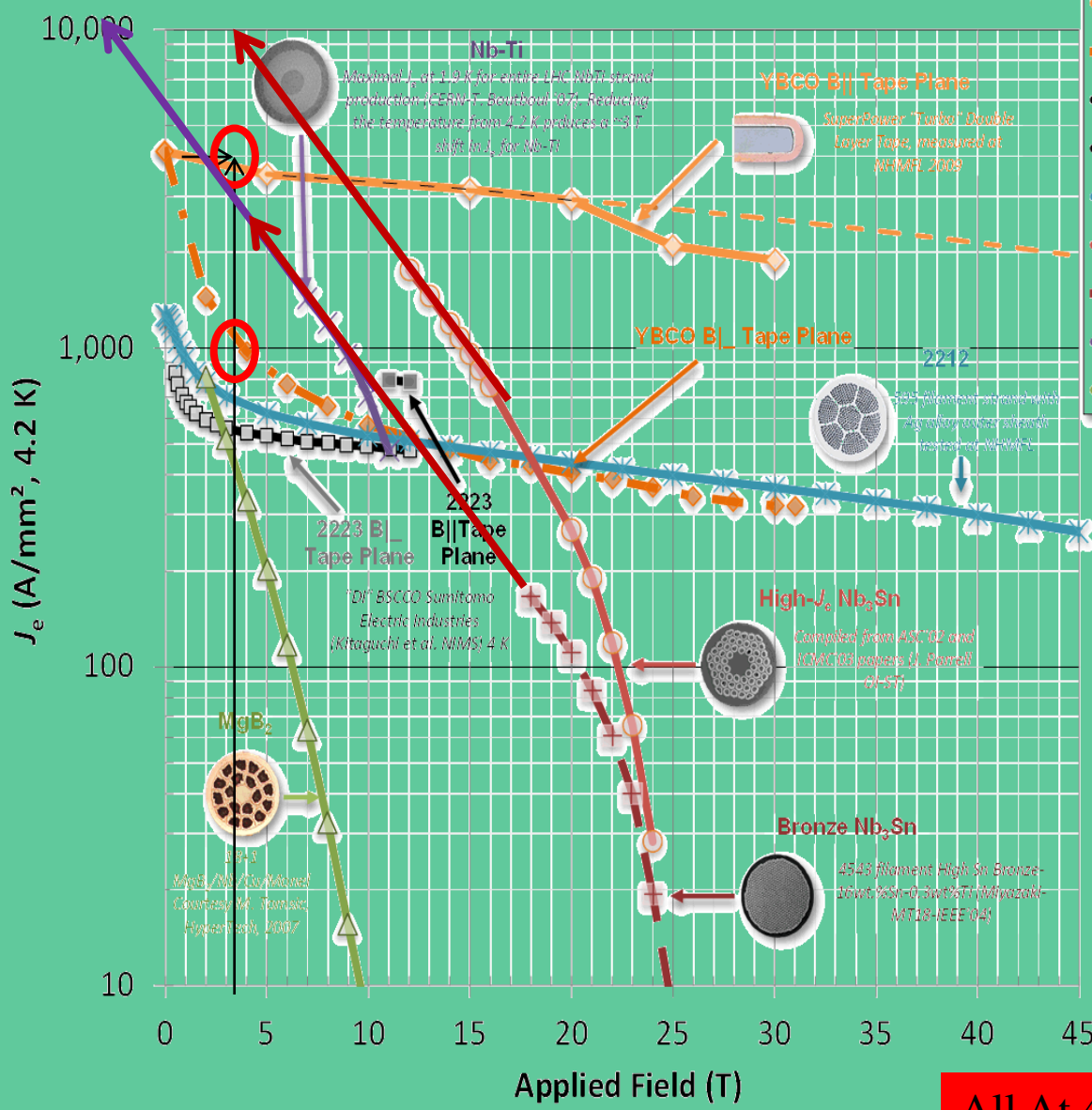
For Bi-based ($\lambda = 25\%$), $J_c = 16,000 \text{ A/mm}^2$

MgB_2 -25% ($\lambda=25\%$), $J_c = 16,000 \text{ A/mm}^2$

YBCO (taking $\lambda = 1\text{-}2\%$), $J_c = 400,000\text{-}200,000 \text{ A/mm}^2 = 20\text{-}40 \text{ MA/cm}^2$



Current Density Across Entire Cross-Section



- YBCO EO
- YBCO FO
- NbTi
- Nb₃Sn
- Bi-2212
- Bi-2223

Well known compilation from Peter Lee, FSU, Applied Superconductivity center

MgB2 seems too low here
 Oxipnictides are lower still

All At 4 K

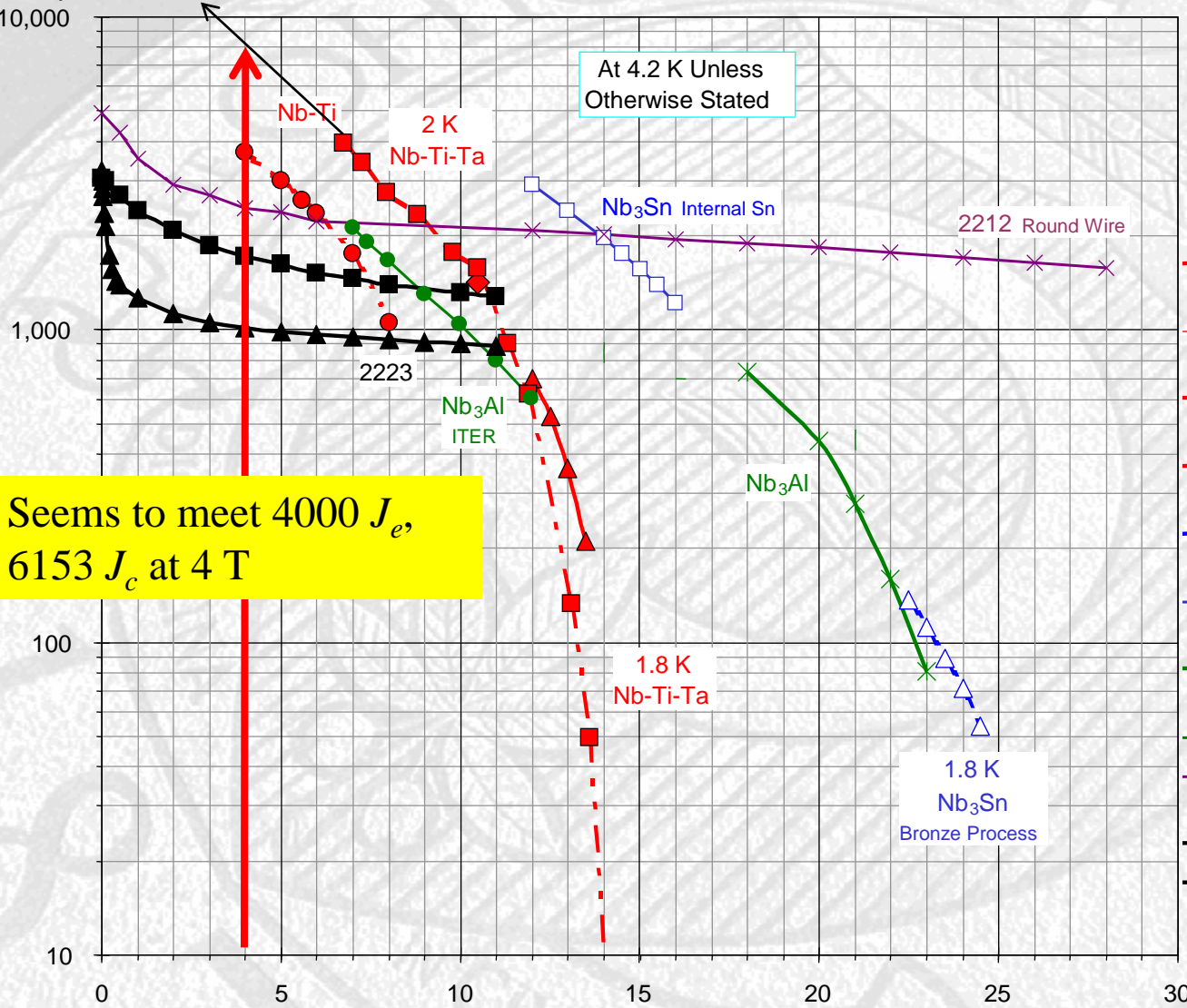
So our options are ..

- NbTi at 4.2 K good performer, but has reached its limit
- YBCO (expensive, inconvenient, only meets J_e in parallel and at 4 K -so may not work)
- Nb₃Sn
- Anything else??

Option 1: we can cool NbTi to 1.8 K

Results are here in J_c , but at 4 T, increase substantially (double?)

Critical Current Density, A/mm²
10,000

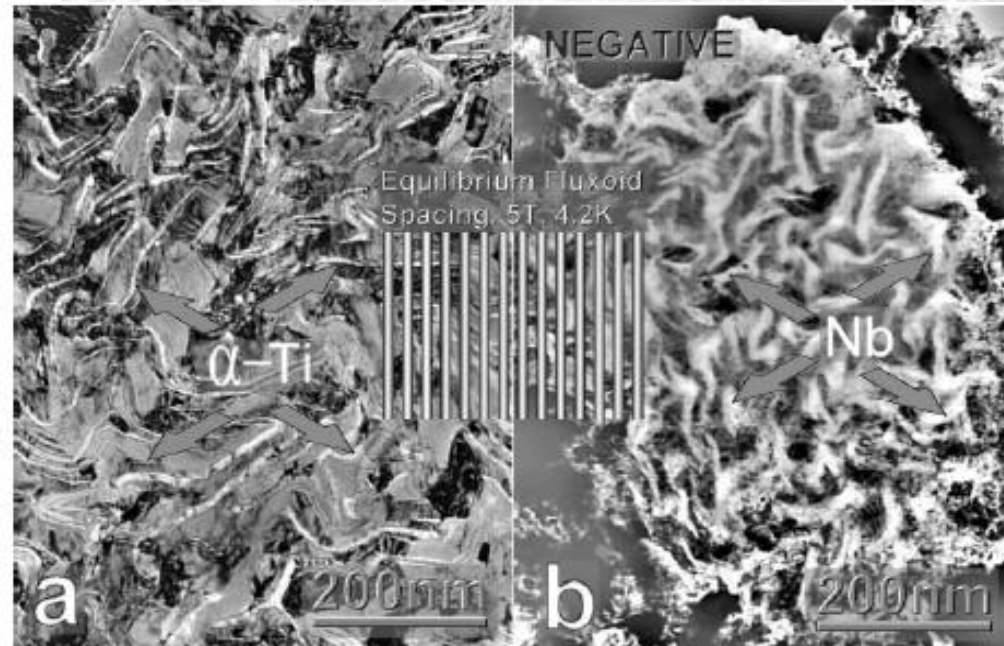
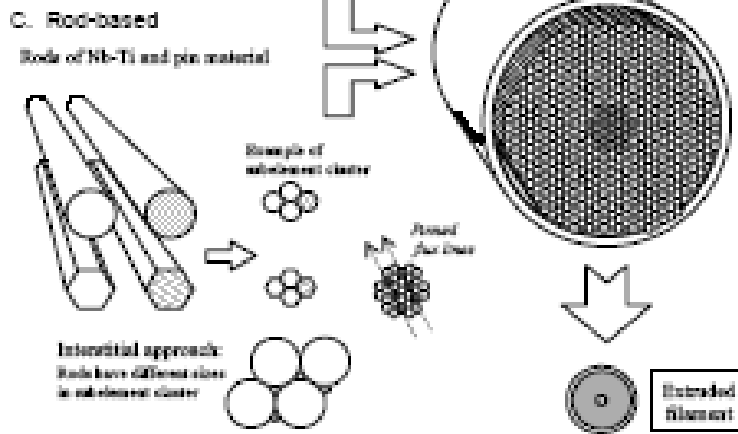
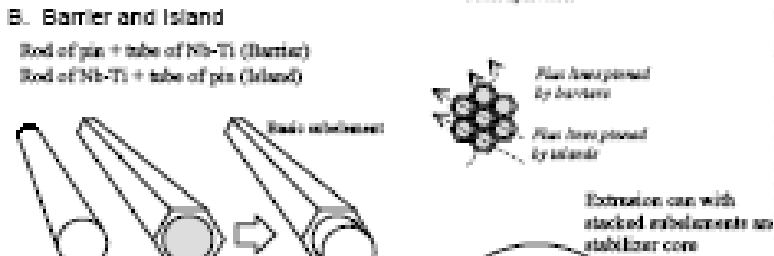
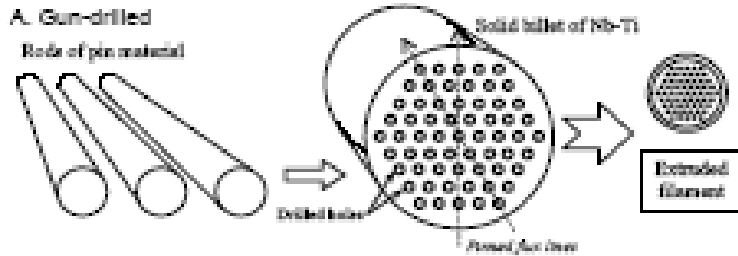


Seems to meet 4000 J_e , 6153 J_c at 4 T

- Nb-Ti: Example of Best Industrial Scale Heat Treated Composites ~1990 (compilation)
- Nb-Ti(Fe): 1.9 K, Full-scale multifilamentary billet for FNAL/LHC (OS-STG) ASC'98
- Nb-44wt.%Ti-15wt.%Ta: at 1.8 K, monofil. high field optimized, unpubl. Lee et al. (UW-ASC) '96
- Nb-37Ti-22Ta: at 2.05 K, 210 fil. strand, 400 h total HT, Chernyi et al. (Kharkov), ASC2000
- Nb₃Sn: Bronze route VAC 62000 filament, non-Cu 0.1μW-m 1.8 K J_c , VAC/NHMFL data courtesy M. Thoen
- Nb₃Sn: Non-Cu J_c Internal Sn OI-ST RRP #6555-A, 0.8mm LTSW 2002
- Nb₃Al: Nb stabilized 2-stage JR process (Hitachi,TML-NRIM,IMR-TU), Fukuda et al. ICMC/ICEC '96
- Nb₃Al: JAERI strand for ITER TF coil
- Bi-2212: non-Ag J_c , 427 fil. round wire, Ag/SC=3 (Hasegawa ASC2000+MT17-2001)
- Bi 2223: Rolled 85 Fil. Tape (AmSC) B||, UW'6/96
- Bi 2223: Rolled 85 Fil. Tape (AmSC) B⊥, UW'6/96



Option 2: NbTi with APCs



L D Cooley† and L R Motowidlo‡

Development of microstructure and Transport Results

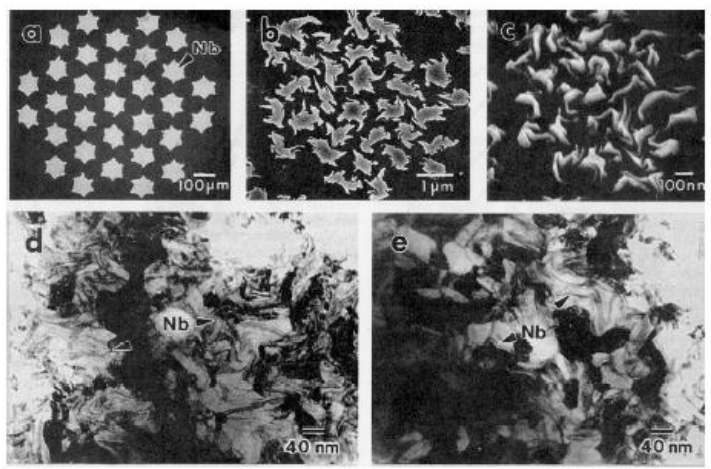
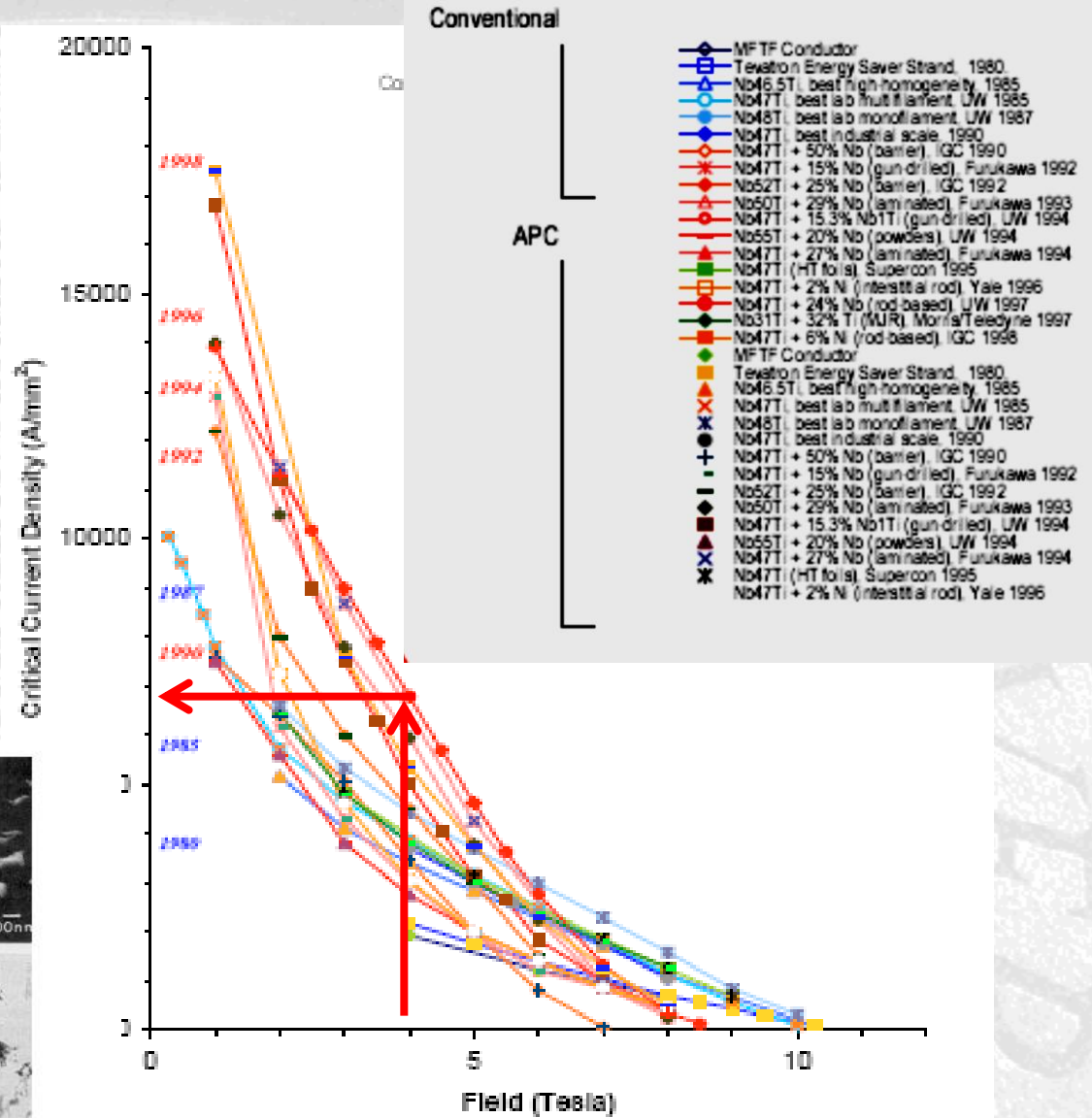
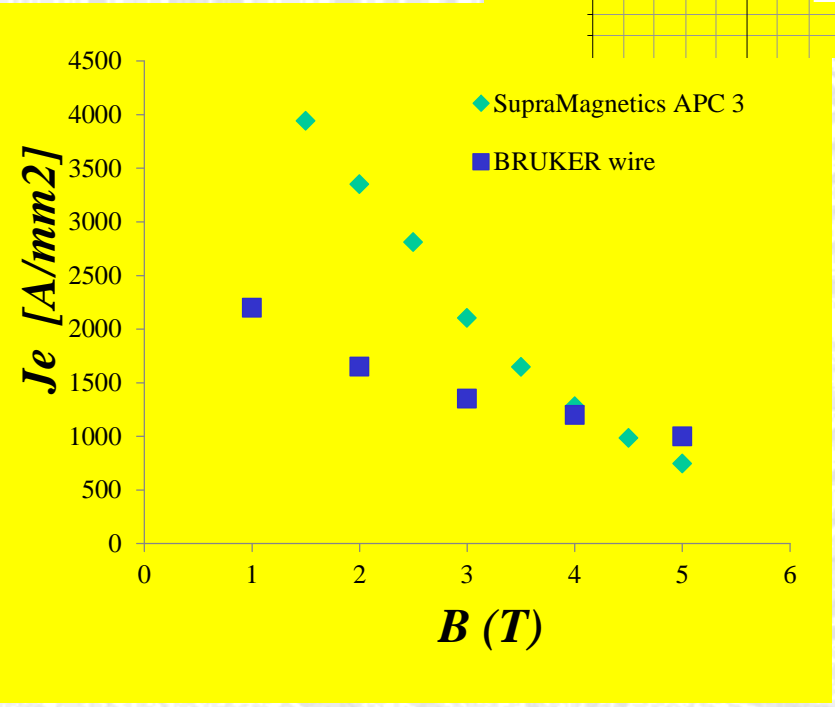
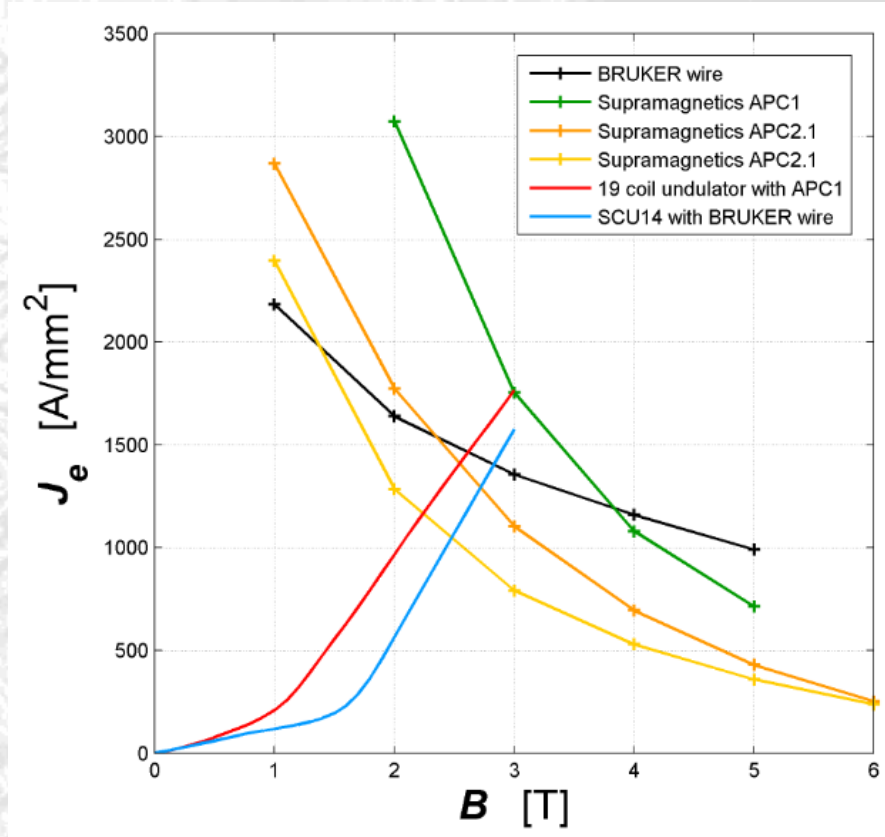
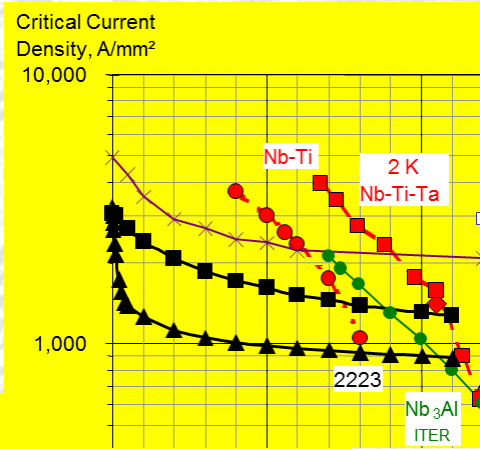


Figure 7. Scanning and transmission electron microscopy images of an Nb pinning centre array in an Nb47Ti matrix at (a) $d_p = 100 \mu\text{m}$, (b) 600 nm , (c) 100 nm , (d), (e) 40 nm . This sequence shows the progressive changes in the shape of the pins from round to highly aspected ribbons. In (d) and (e) the actual pin thickness is 1–15 nm, much less than the calculated pin diameter from equation (1). (Imaged obtained from [56]).

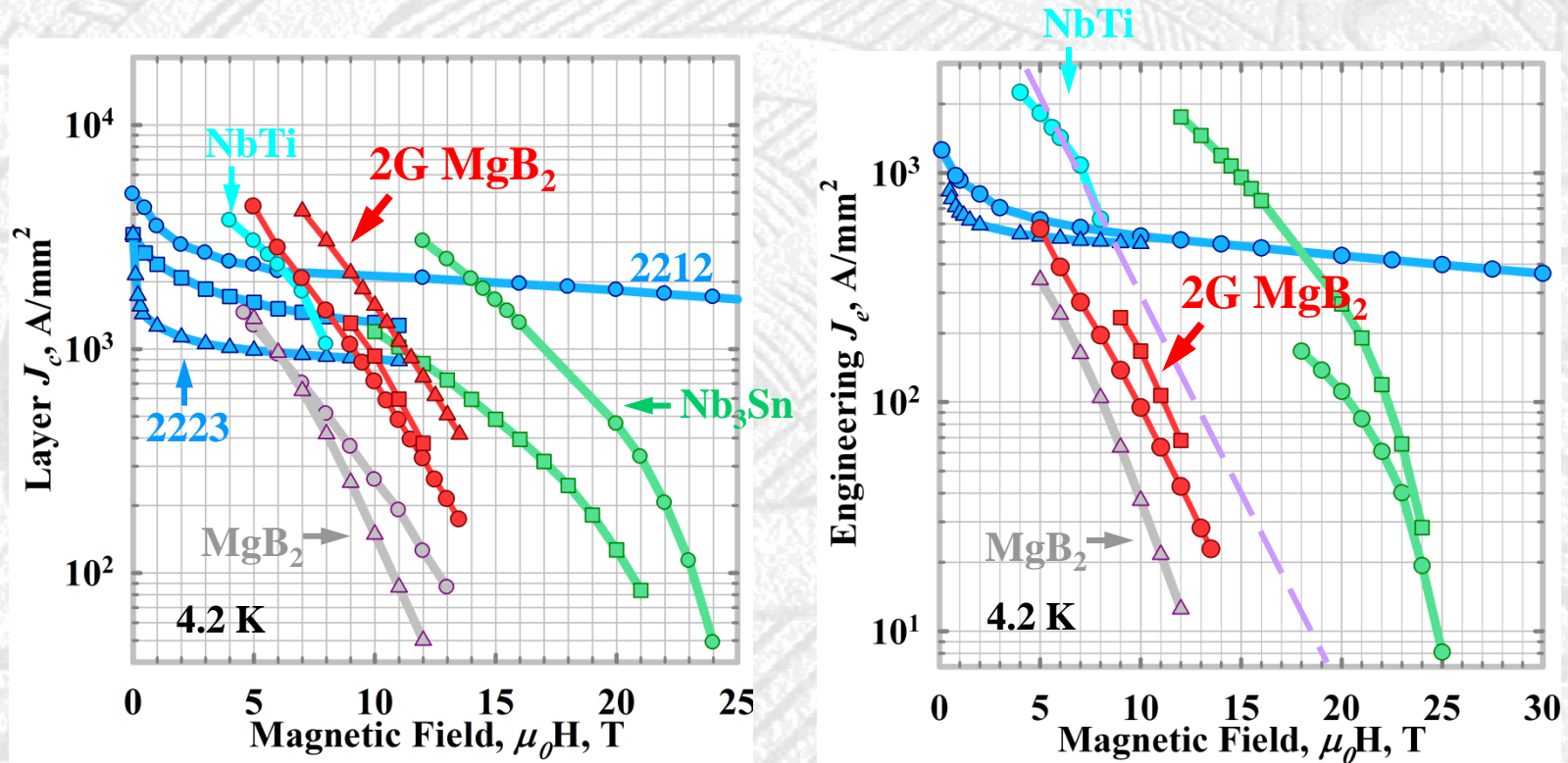
APCs—Can beat NbTi, but only below 3 T

Because J_c increases rapidly with dropping B , but fill factor is lower



Recent Advances in MgB₂ – Huge increases --

Second generation MgB₂ wires: both improved critical current density J_c and engineering J_e . Not able to beat NbTi wrt J_e yet, but is moderate cost, and could allow > 4 K operation



- 2G IMD Barrel
- 2G MgB₂ (2% C)
- ▲ 2G MgB₂ (3% C)
- ▲ PIT MgB₂ Wire
- MgB₂ Tape (Grasso)
- NbTi (Larb 96)
- Nb₃Sn ITER
- Nb₃Sn (Internal Sn)
- ▲ 2223 (B-perpendicular)
- 2223 (B-parallel)
- 2212 Round Wire



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So...

- Option 1: 1.8 K NbTi
- Option 2: APC NbTi, but only for designs with B 3 T and below
- Option 3: Nb₃Sn

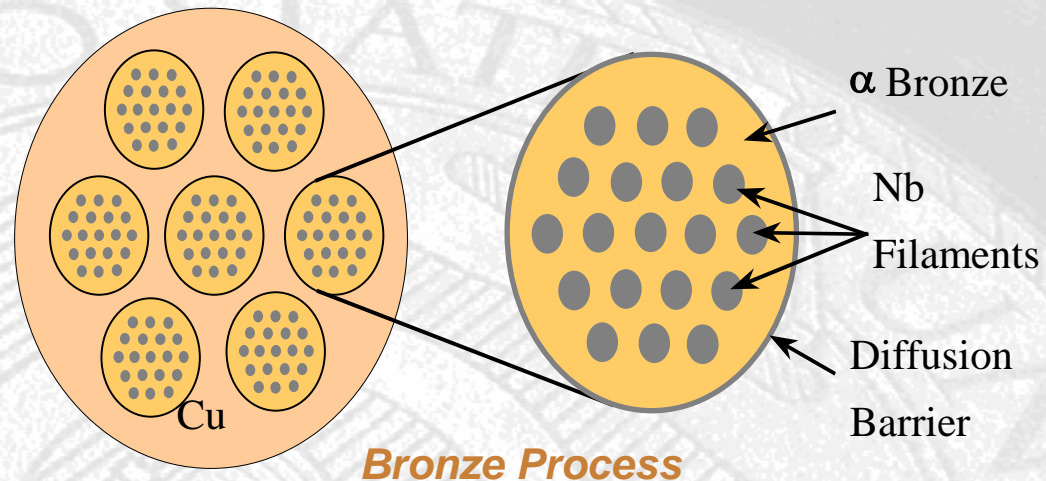
Flavors of Nb₃Sn

1. Bronze Route
2. Rod-In-Tube, Fusion-Type
3. Rod-in-Tube, HEP Type
4. Powder-In-Tube
5. Tube

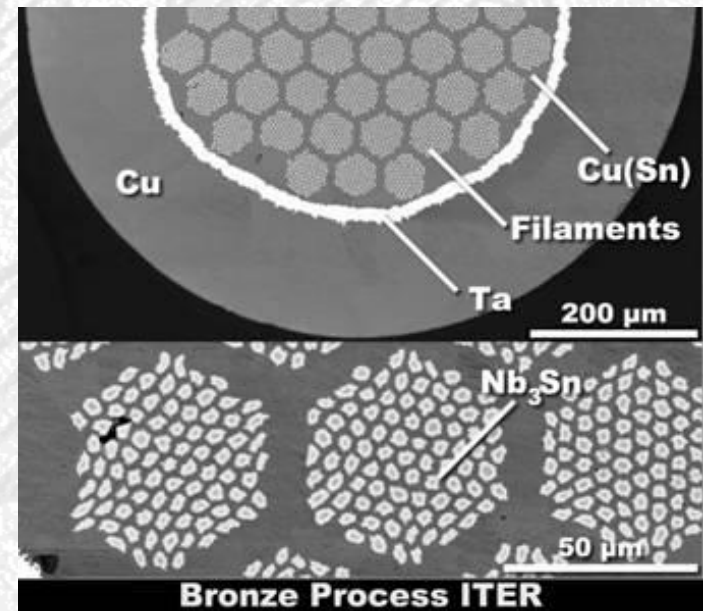
But, Nb₃Sn comes in a variety of different flavors...



The Bronze Process



- Bronze route (Nb rods in Cu-Sn alloy)
 - Cu dissolves 9at.%Sn maximum while remaining single phase and ductile
 - Cu7.5at.%Sn used for years
 - NMR conductors see advantage, even for additional mechanical complexity in going to 8-8.5%Sn

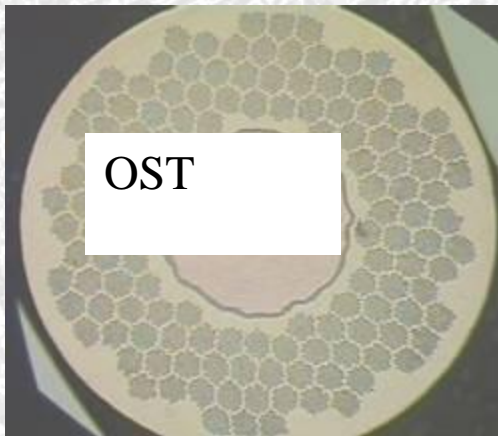
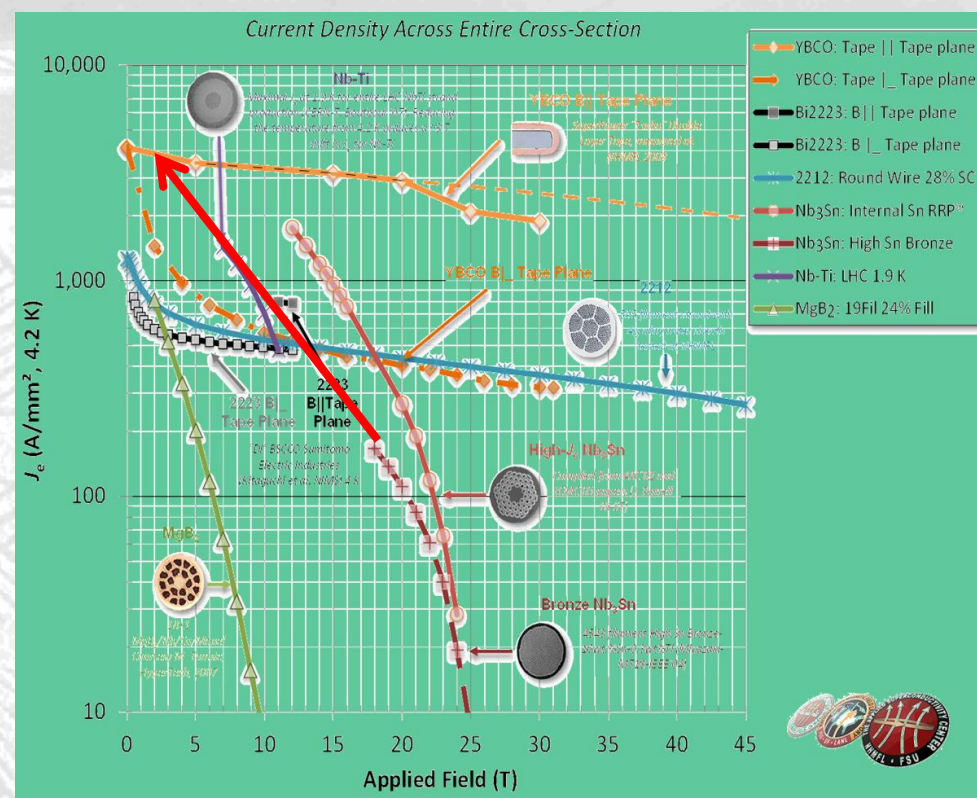


Bronze Process

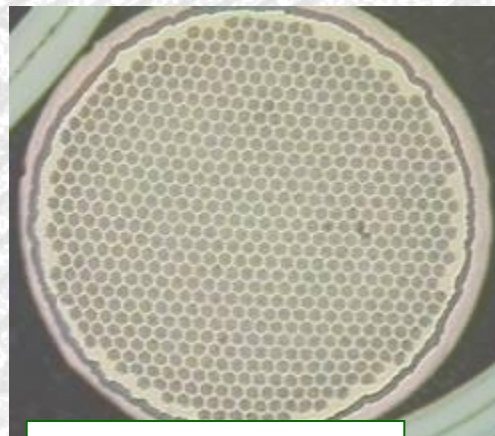
Limited level of Sn limits amount of Nb that can be used and lessens final A15 stoichiometry

Annealing during wire drawing required because of work hardening

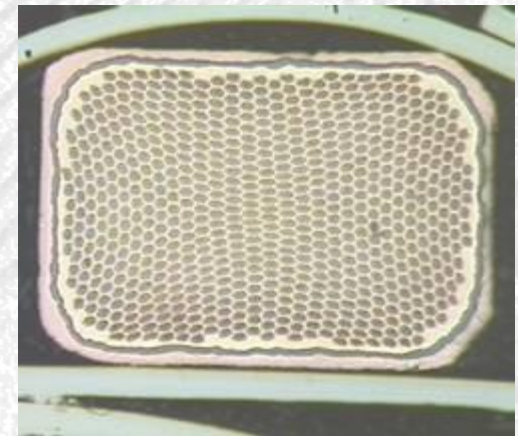
A bit lower than we want for Undulators



Internally Stabilized Bronze



Externally Stabilized Bronze



Externally Stabilized Bronze

Fusion Type RIT

Bronze is OK - but we can't cram enough Sn in (limited to 9 at%)

This limits B_{c2} and J_c

We can get around this by inserting ductile Cu/Sn composites and then in-situ reacting after wire drawing

In this version of RIT, a Cu rod drilled full of holes, and Nb rods are inserted into the Cu with one large Sn rod in the center

This leads to J_c values higher than bronze, but not usually much higher

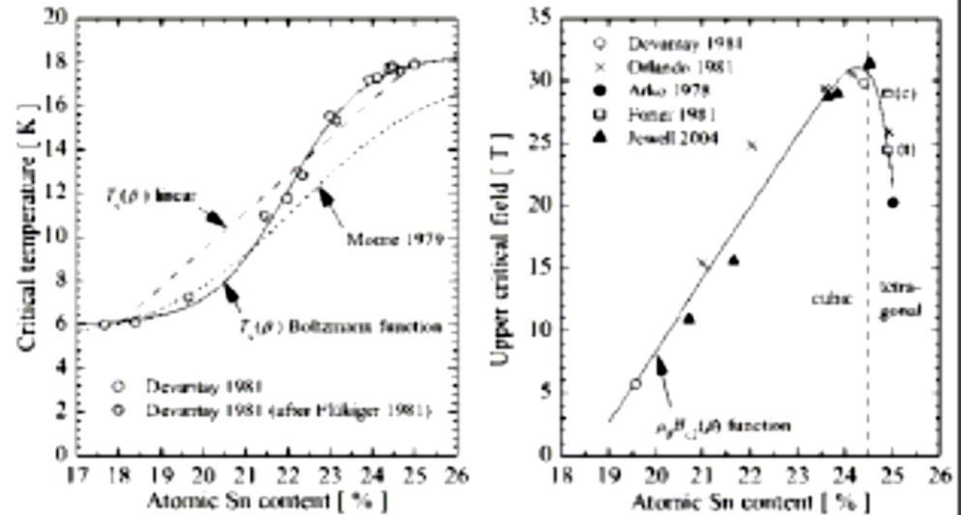
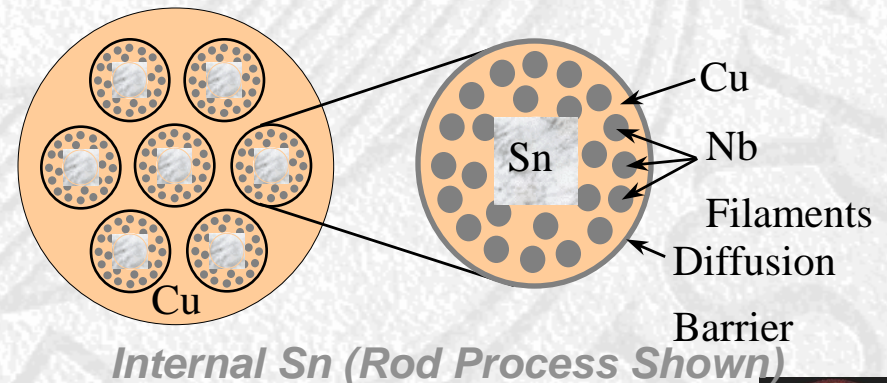
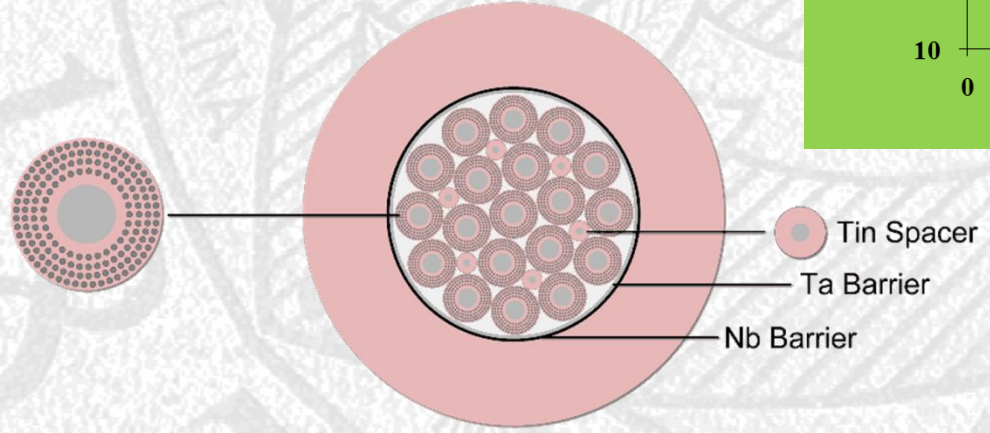
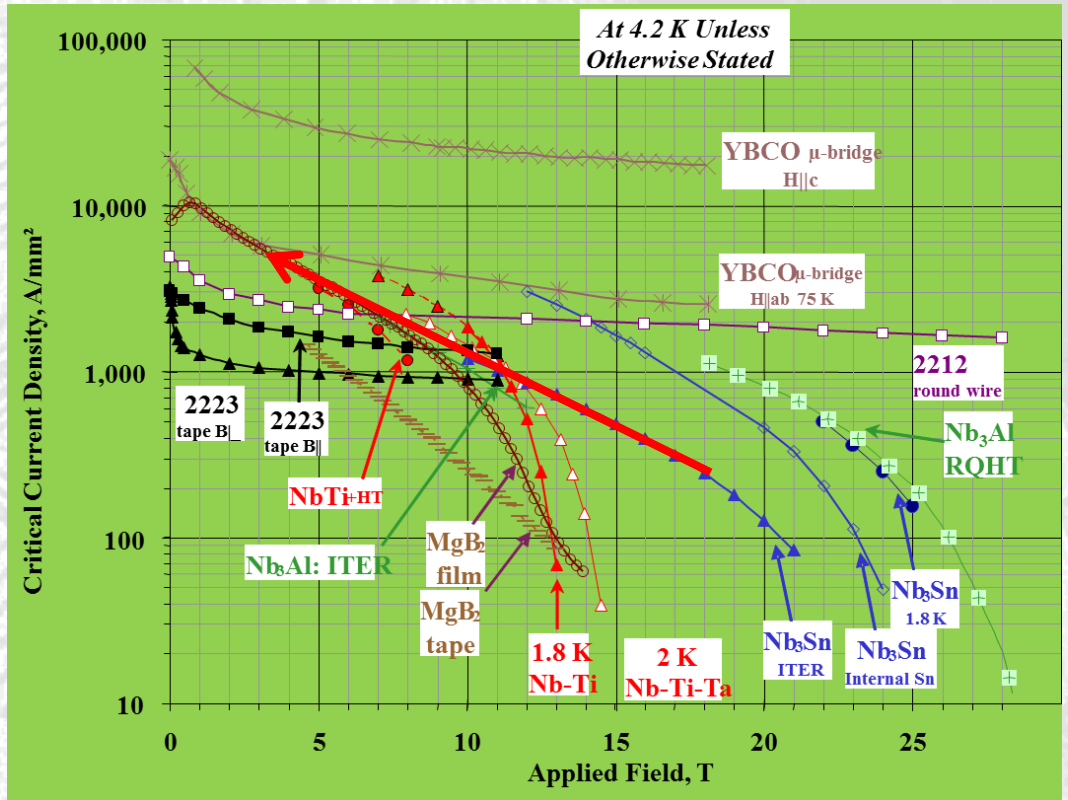
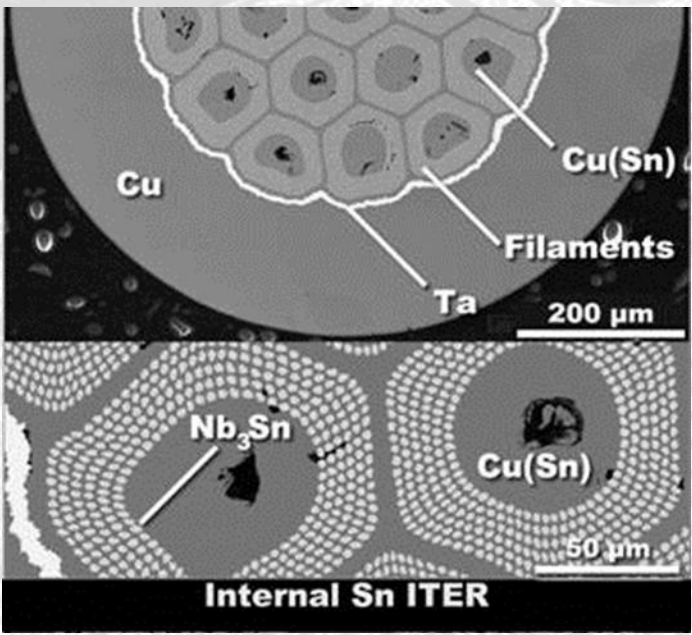


Figure 2.2 Variation of the critical temperature and upper critical field with atomic Sn content (reproduced from the work of A. Godeke [21]).



Fusion type RIT



Getting closer, but need a bit more!

HEP Type RIT, i.e., Internal Sn, RRP, Distributed barrier

One problem with Fusion-type RIT, where the rods are put in drilled holes, is that the hole density is limited, so the final amount of Nb_3Sn is limited

In HEP type Nb_3Sn , Nb rods with thin Cu cans are stacked around a Cu center.

This is extruded, and then a hole is drilled, and the Sn is packed in

Has very high J_c , but can be unstable in the regime of interest for undulators

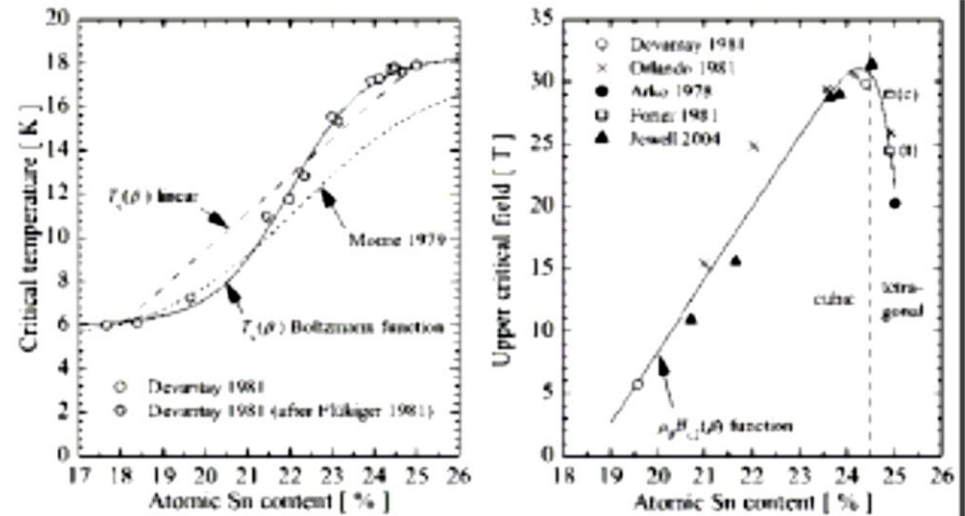
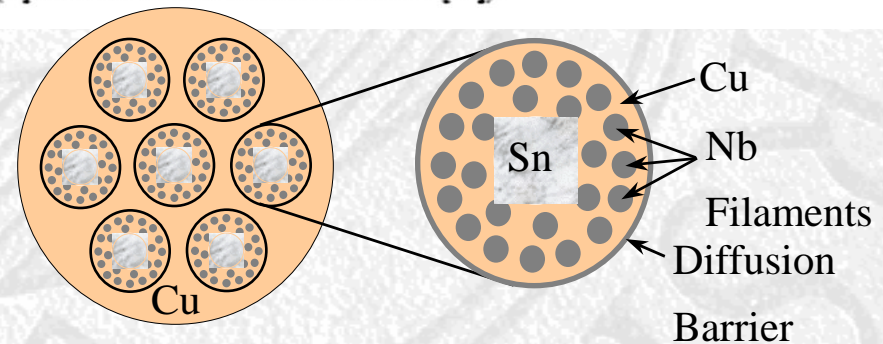
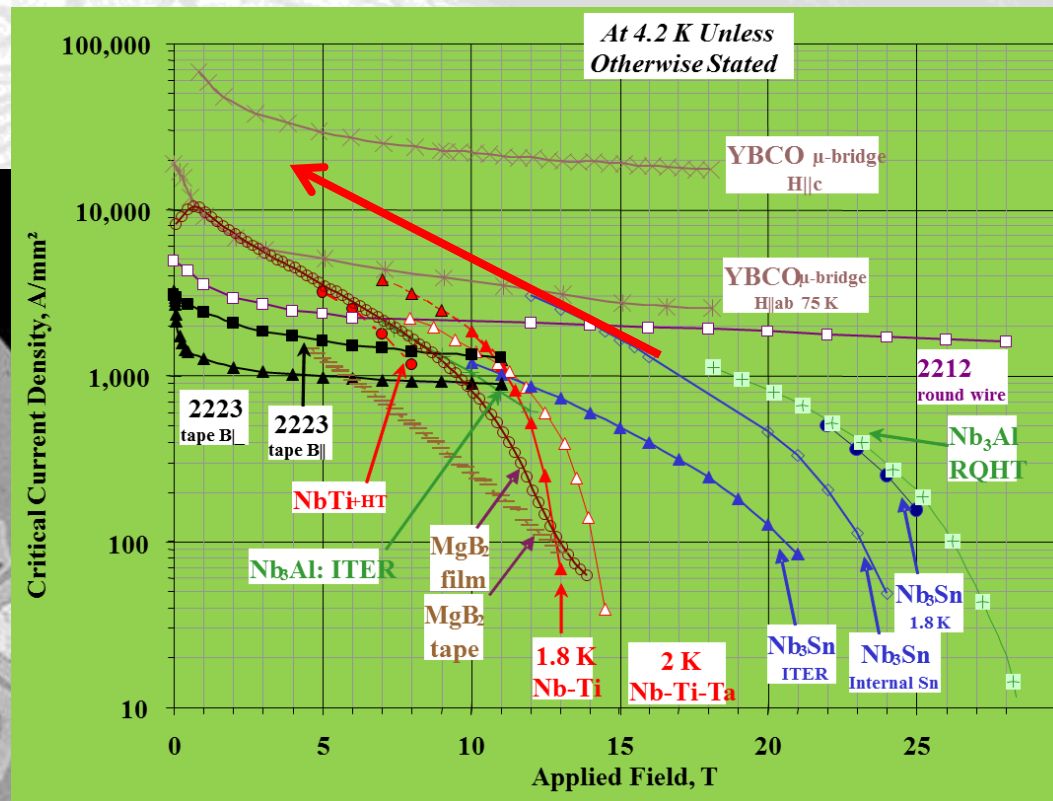
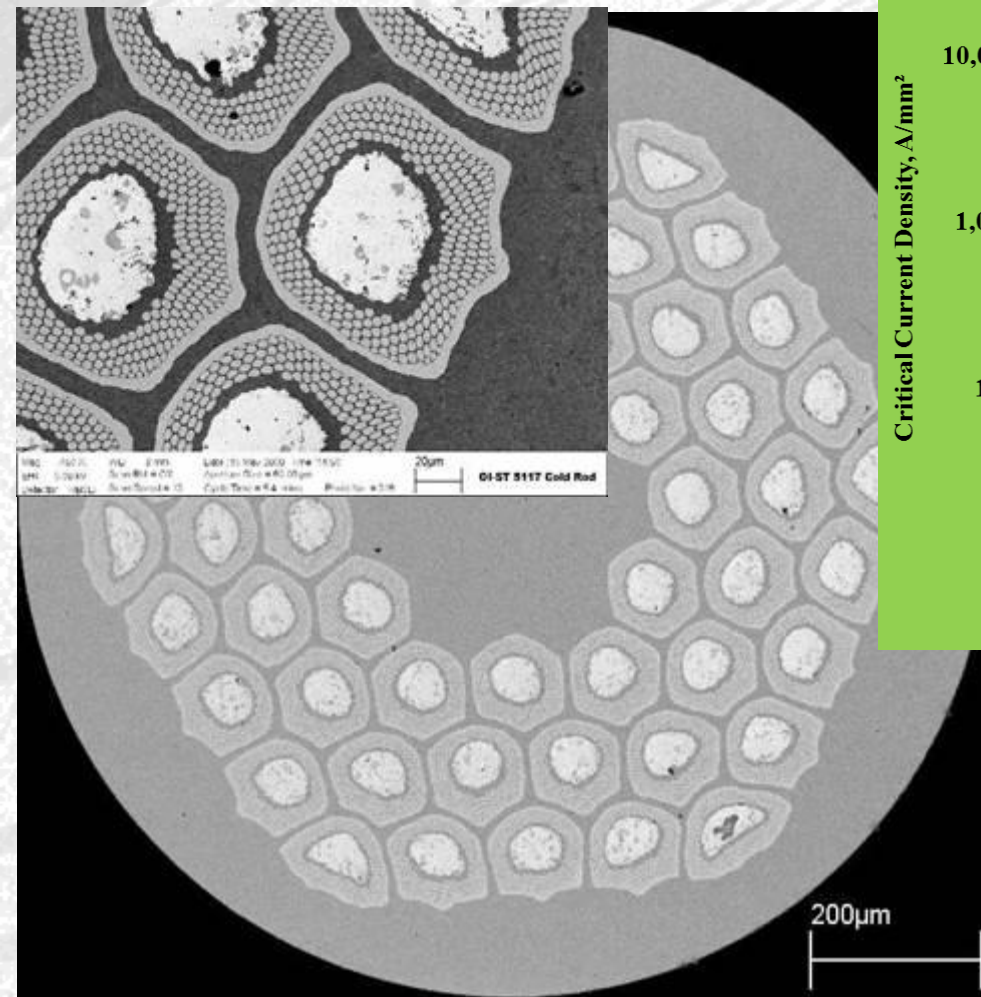


Figure 2.2 Variation of the critical temperature and upper critical field with atomic Sn content (reproduced from the work of A. Godeke [21]).



Internal Sn (Rod Process Shown)

Oxford's version of the RIT

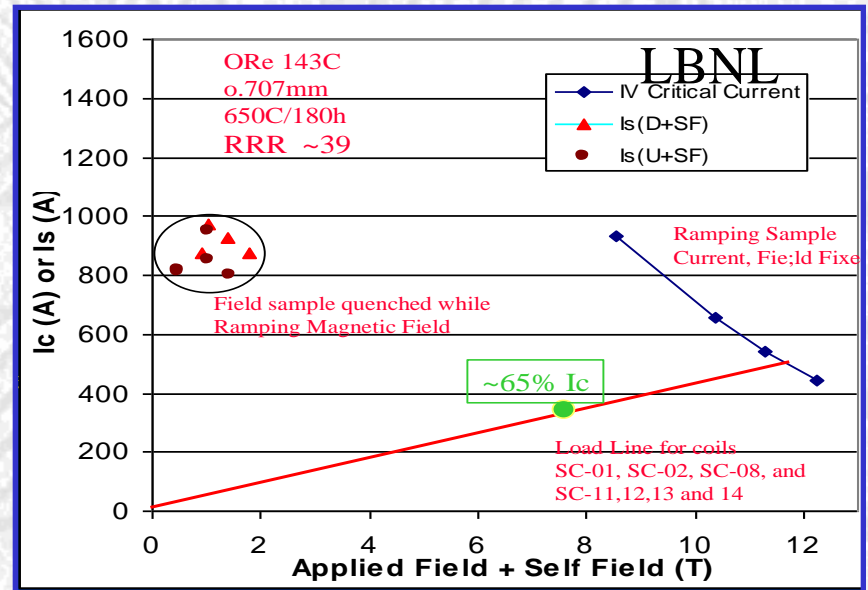
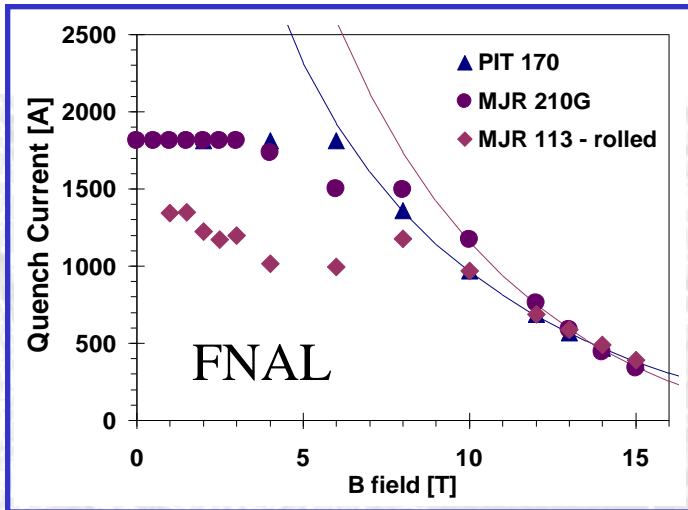
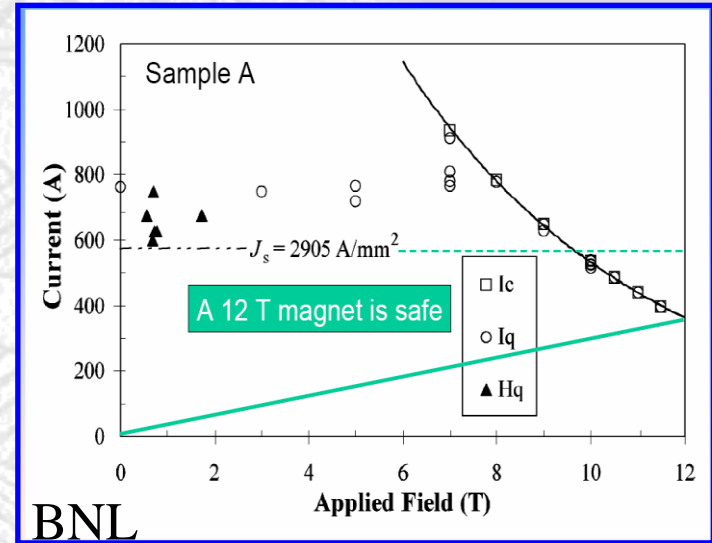
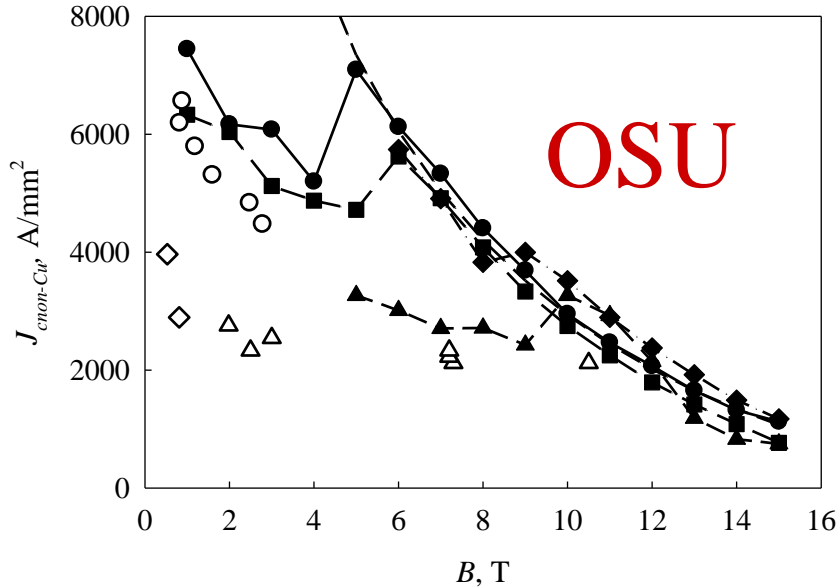


Performance is now well within the regime we need, but we will find it is not stable in the field range of interest

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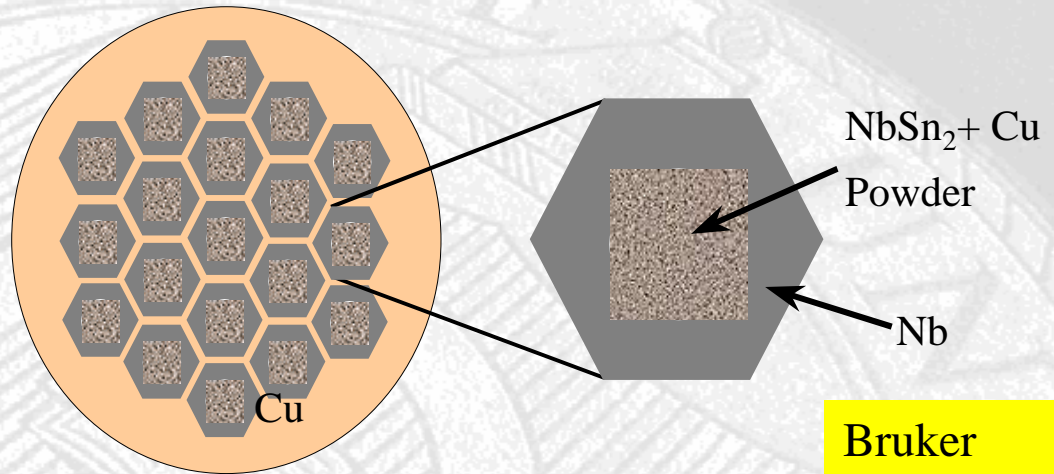


Instability of HEP type RIT at lower B

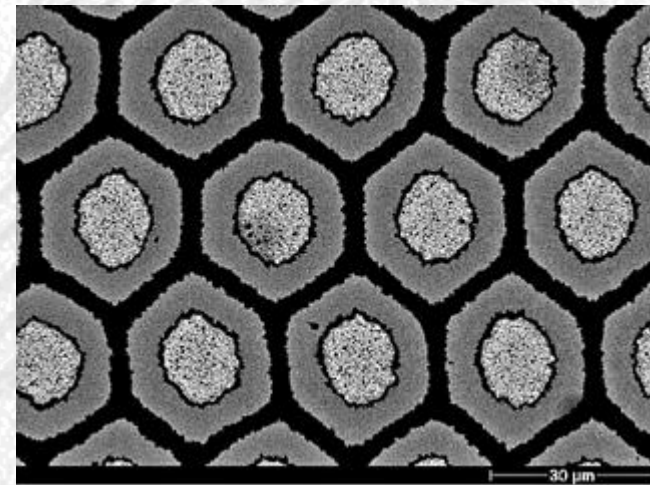
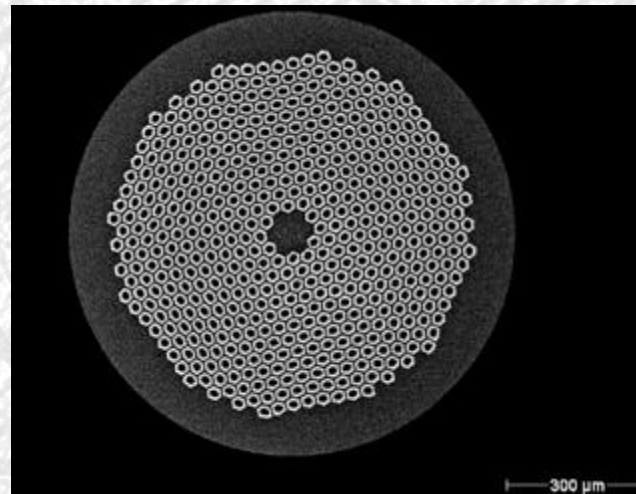


The PIT Route to Nb-Sn Wires

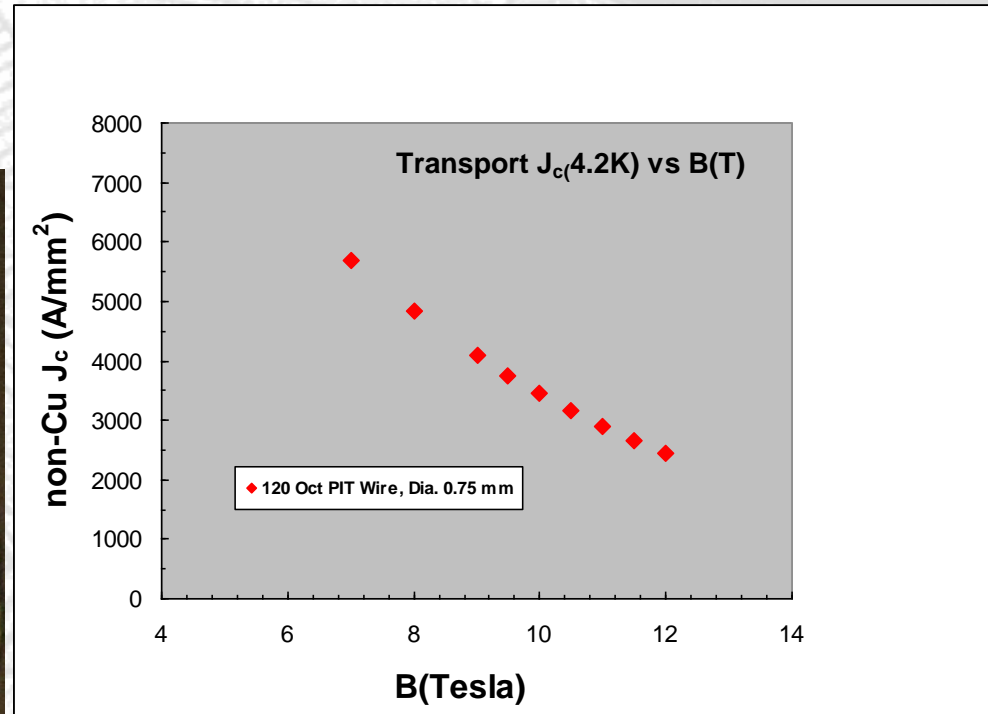
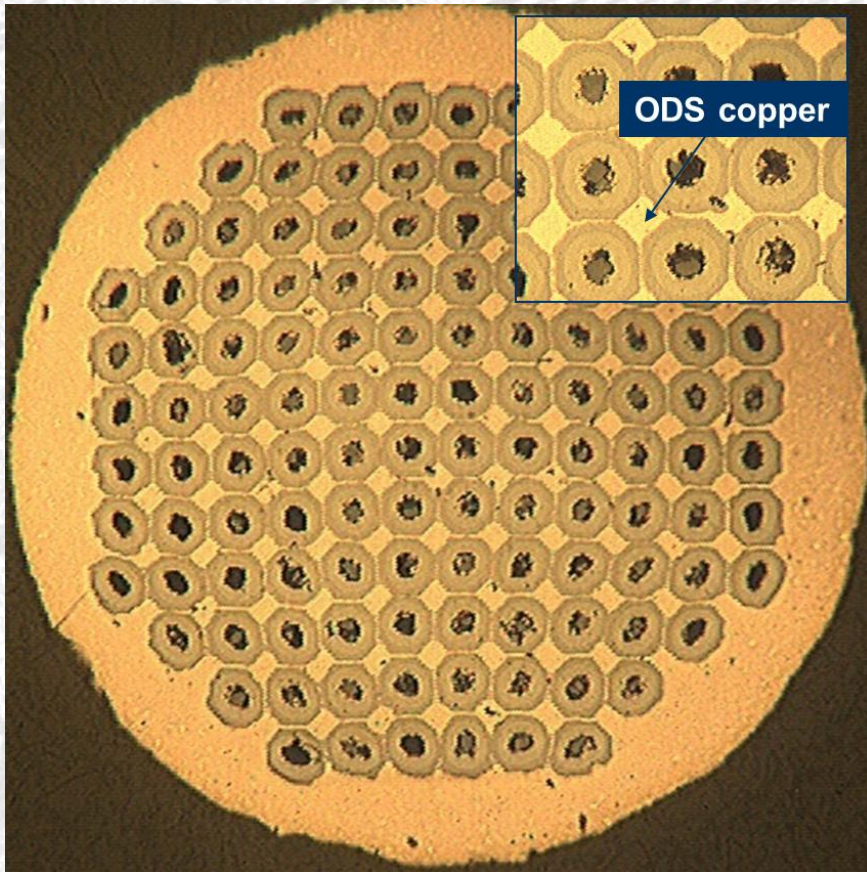
- Powder in Tube method places NbSn_2 inside Nb tubes



PIT – Powder in Tube



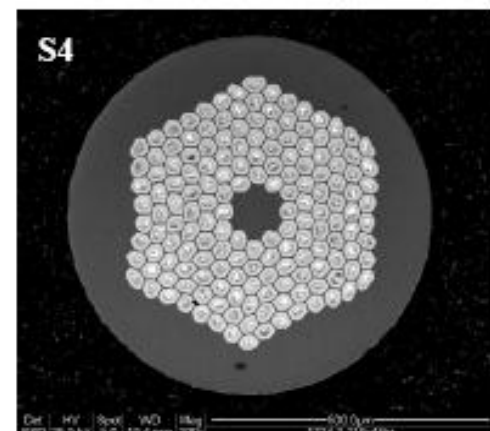
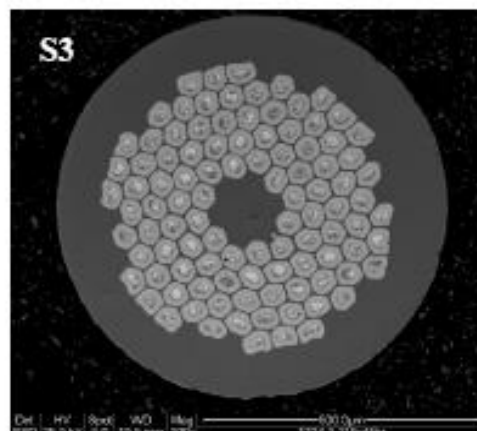
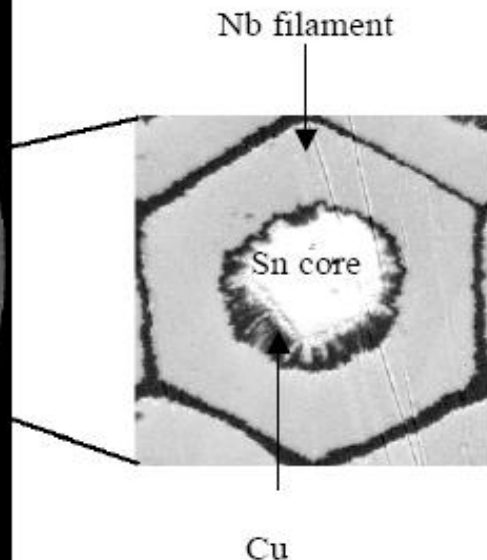
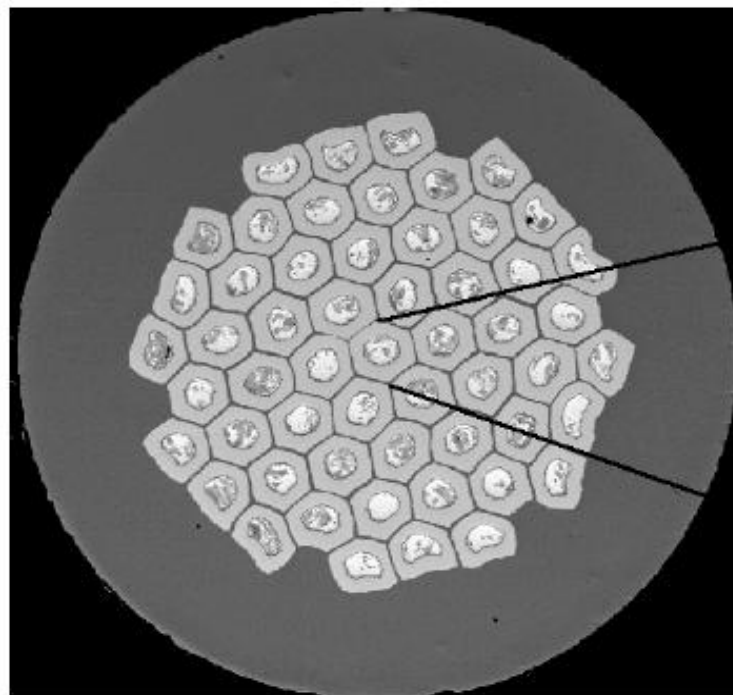
Octagonal Version of PIT



In the regime of interest
Issue to control powders

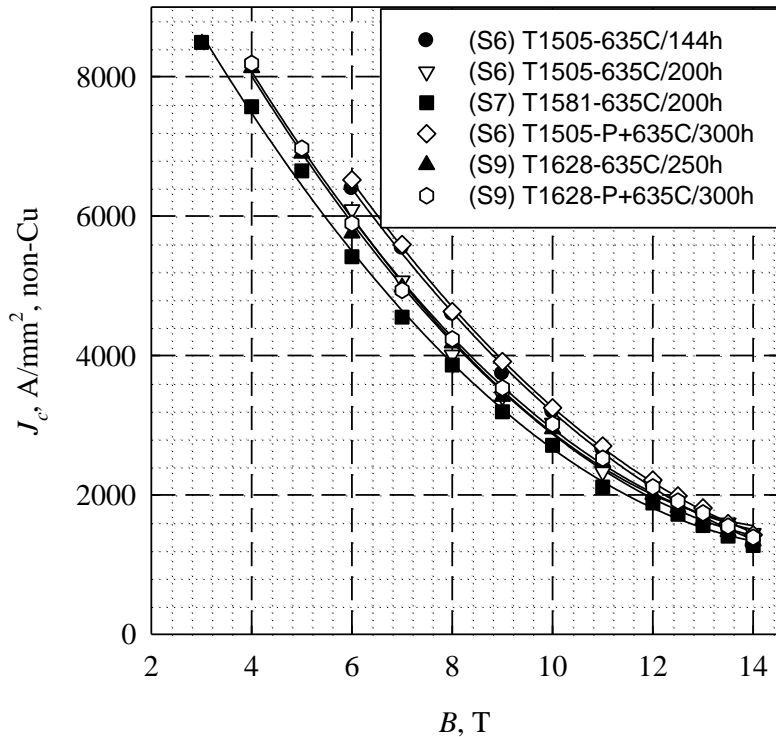
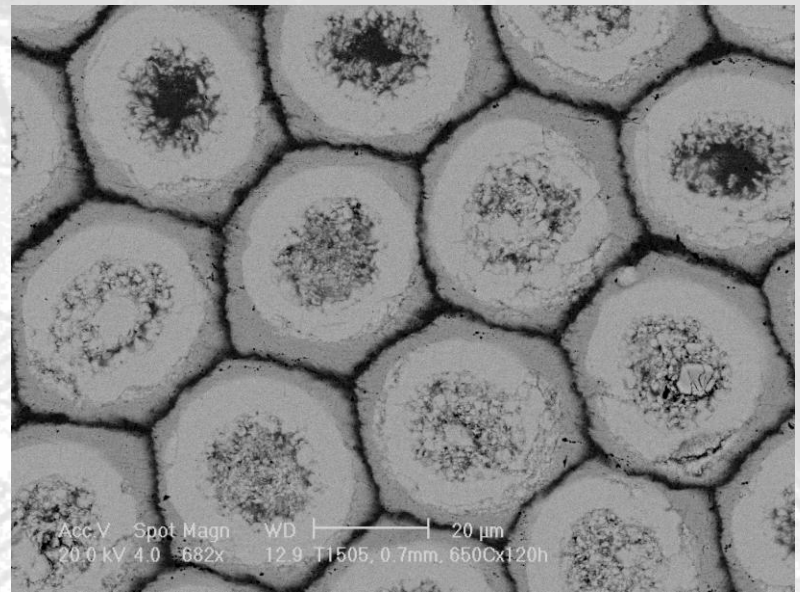
Tube Type Conductors

A Simple structure of Sn/Cu/Nb drawn and then



As developed by Supergenics, Hyper Tech, Global

Tube Conductor Transport



Also hitting the regime of interest
For undulator work

2250 A/mm² at 12 T in 217 stack conductor



Department of Materials Science and Engineering



Some final Comments and Considerations

- NbTi conductors have maxed out, unless we drop to 1.8 K
- Of the HTSC, YBCO seems most relevant, but seem to not quite hit targets even at 4 K
- MgB₂ making major strides, but not yet at J_e of NbTi
- APC has high J_c , especially at moderate to lower fields, but lower fill factor leads to it's beating standard NbTi only 3T and below
- Nb₃Sn is promising, but is a wind and react conductor, so must account for insulation when computing the final winding J_w
- Of the Nb₃Sn's, Bronze and Fusion type RIT are not high performance enough
- HEP type Nb₃Sn has more than enough performance, but has stability problems
- PIT and Tube Nb₃Sn are of interest for Undulator application